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TABLE OF CONTENTS

A Novel 600mm Panel Interposer with 300mm Panel Assembly Approach for Advanced Packaging Solution in HPC and AI Applications	1
<i>Teck Chong Lee, Yungshun Chang, Ping-Feng Yang, Lihong Cao, Wiwy Wudjud, Powei Lu, Yihsien Wu</i>	
Multi Stacked FOWLP utilizing Extreme Aspect Ratio Cu Post for Mobile on-Device AI Memory Solution	7
<i>Eun Young Lee, Sangkyu Lee, Woosang Jung, YongJin Seol, Yieok Kwon, Myeonghan Bae, Dong-Jun Choi</i> <i>EunJi Jang, So Hyun Lee, Jeongseok Mun, Sungoh Ahn, Won Kyung Choi</i>	
The Study and Challenges of Ultra-thin Chip Module for Fan-out Embedded Bridge Die Package (FO-EB)	13
<i>Kuei Hsiao Kuo Frank, Jui Teng Hung, Derrick Dai, Chun Sheng Ho, Feng Lung Chien</i>	
Progress towards a fine-pitch multi-layer organic substrate enabled by fan-out technology	19
<i>Georgios C. Dogiamis, Matthew T. Magnavita, Mike Naujokaitis, Robert Naujokaitis, Gregory Johnson</i> <i>Stanislau Niauzorau, Leslie Hwang, Timothy Takeuchi, Binh Duong, Craig Bishop, Jason Conrad</i>	
A Novel Membrane-Based Adaptive Pressure Curing System for Warpage Suppression in Advanced Packaging	24
<i>Huan-Ping Su, Ming-Hua Hsu, Chih-Horng Horng</i>	
Metal-Enhanced Waffle Wafer Design for Thermomechanical Warpage Reduction in Fan-Out Wafer-Level Packaging	31
<i>Bonghak Lee, Sang Won Yoon</i>	
Additive Fan-Out Packaging for Discrete Components	37
<i>Arjun Wadhwa, Edsger C. P. Smits, Milan Saalmink, Marieke Burghoorn, Iris Kerkhof, Ruben Pranger</i> <i>Luigi Gjergjaj, Bart van Goor, Francesca Chiappini, Jeroen van den Brand</i>	
Proposal of a Novel Opto-Electronic Fan-Out Wafer-Level Packaging Based on Optical RDL and Opto-Chiplets	43
<i>Siim Heinsalu, Fumi Nakamura, Satoshi Suda, Akihiro Noriki</i>	
High-Density, Energy-Efficient CPO Platform with PIC-in-Mold Interposer Architecture for AI/ML Data Centers	48
<i>Sajay Bhuvanendran Nair Gourikutty, Wu Jiaqi, Zhonghua Yang, Mihai Rotaru, Ji Lin, Han Yong</i> <i>Chia Lai Yee, Sharon Lim, San Sandra, Chai Tai Chong, Surya Bhattacharya</i>	
Photonic-Electronic Integration on Glass Substrate with Temperature-Stabilized Vertical Optical Coupling by Resin-Encapsulated Collimation Mirror	55
<i>Shingo Nakamura, Yasutaka Mizuno, Kunio Kobayashi, Takeru Naito, Tetsuya Nakanishi, Hiroshi Uemura</i> <i>Keiji Tanaka, Katsumi Uesaka, Mio Emura, Mami Miyairi, Yoshikatsu Ishizuki, Yoichiro Kurita</i>	
Thin-Film Lithium Niobate Hybrid Integration for Co-packaged Optics	61
<i>Zhixing Lin, Tam Huynh, Ayed Sayem, K.W. Kim, Cuong Tran, Yang Liu, Manohar Bongarala</i> <i>Sarwesh Parbat, Rishav Roy, Ting-Chen Hu, Alaric Tate, Mark Cappuzzo, Rose Kopf, Alexander Rylyakov</i> <i>Mark Earnshaw</i>	
High-Density Integration of III-V Devices and EICs using Vertical-Coupled Photonic Packages with Glass-IP and Redistribution Layers	68
<i>Kei Masuyama, Mizuki Shirao, Shinji Araki, Kiyotomo Hasegawa, Shinya Okuda, Seiu Higashide</i> <i>Nobuo Ohata</i>	

A 106-Gb/s × 8-Channel 1060-nm Single-Mode VCSEL-Based Ultra-Compact CPO Transceiver enabling 2-km Parallel-Optical Links	73
<i>Wataru Yoshida, Yuto Iwane, Kazuya Nagashima, Kzutaka Takeda, Sho Yoneyama, Hideyuki Nasu Fumio Koyama</i>	
Design and Packaging of a DWDM CW-DFB Laser Array for Co-Integrated Optical Interconnects	79
<i>Nandish Mehta, Ward Lopes, Benjamin G. Lee, C. Thomas Gray, Ryosuke Hatai</i>	
Hybrid bonding with ultra-low temperature annealing: morphological and electrical validations	85
<i>Margot Faure, Agathe Lerat, Pablo Renaud, Floriane Baudin, Maria-Luisa Calvo-Muñoz, Hadi Hijazi Frank Fournel, Christophe Dubarry</i>	
Pressure-less Cu/Polymer Hybrid Bonding at Low Temperature and Fine Pitch using a Novel Polymer Adhesive with Precisely Controlled Composition	91
<i>Ryo Hayakawa, Yuzo Nakamura, Satoshi Otsuka, Hajime Kato, Shigetaka Hori, Yutaka Hisamune Satoshi Inada, Chih-Jing Hsu, Yung-Sheng Lin, Jen-Chieh Kao, Chin-Pin Hung, Yung-I Yeh</i>	
Reliable Low-Temperature (≤ 250 °C) Cu/Dielectric Hybrid Bonding for High-Bandwidth Memory (HBM) Stack Integration	97
<i>Tran Van Nhat Anh, Prayudi Lianto, B.S.S. Chandra Rao, Chaeun Lee, Fujino Masahisa Nicholas Chua Boon Leong, Rong Ji, Ming Lin, Yong Hong Derrick Tan, Vempati Srinivasa Rao Navab Singh</i>	
Low-Temperature Chip Scale Cu-Cu Hybrid Bonding by Electroless Ag Passivation	104
<i>Cheng-Yan Yang, Ming-Hsuan Hsieh, Po-Shao Shih, Wei Choong Lee, Yu-Hsiang Lu, Yun-Ching Hung Yung-Sheng Lin, Chen-Chao Wang, Chih-Pin Hung, C. Robert Kao</i>	
Enabling Low-Temperature Fine-Pitch Hybrid Bonding: Role of Nanocrystalline Copper Microstructures and Pre-Bond Surface Treatments	109
<i>Mathieu Loyer, Mathilde Gottardi, Christelle Rey, Emilie Deloffre, Sebastien Petitdidier Maria-Luisa Calvo-Muñoz</i>	
Polymer Fillet Integration to Improve Die Thinning and Inter-die Gap Fill Yield and Reliability in Die-to-Wafer Hybrid Bonding	116
<i>Alyssa N. Yaeger, Cristina Camagong, Roy Yu, Katsuyuki Sakuma</i>	
Scalable Low-Temperature Bonding for Packages Targeting Large-Format Interposers: High Throughput and High Reliability	122
<i>Sadaaki Katoh, Takeshi Saito, Keiko Ueno, Daisuke Hashimoto, Haruya Suzuki, Kiyoshi Oi, Goro Hasui</i>	
100-nm-level Post-Bond Accuracy and High-Yield Die-to-Wafer Hybrid Bonding System Using Non-Contact Die Transfer	128
<i>Kentaro Mihara, Takashi Hare, Hirofumi Sakai, Shimpei Aoki, Fumihiko Inoue, Akira Uedono Murugesan Mariappan, Hiroyuki Hashimoto, Takafumi Fukushima</i>	
A Study of Chipllet Distortion in Chip-to-Wafer (C2W) Hybrid Bonding	136
<i>Yi Shi, Charles El Helou, Mohammadreza Yaghoobi, Sheena Benson, Siyan Dong, Khant Minn Tushar Talukdar, Haris Khan Niazi, Chytra Pawashe, Lance Hibbeler, Brandon Rawlings Aleksandar Aleksov</i>	
INTERCEPT™ - A Nondestructive Known Good Die Testing Probe and Reworkable Substrate Enabled by Liquid Metal Patterning	142
<i>Samuel Wang, Hsuan-En Lee, Hsiao-Chen Lin, Alexiy Samoylov, Mansi Sunil Sheth, Jui-Han Liu Vineeth Harish, Subramanian S. Iyer</i>	

Assembly Process Optimization to Reduce Particle-Induced and non-Particle-Induced Voids in Chip-to-Wafer Hybrid Bonding	147
<i>Ling Xie, Ser Choong Chong, Hipona Randy Tupaen, Ignatius Lim, Vasarla Nagendra Sekhar Mishra Dileep Kumar, B.S.S. Chandra Rao, Vempati Srinivasa Rao, Fredimar Soliven, Evagelista Roy Chong Wei Lun, Nithyananda Hegde, Pavel Seroglazov, Hannes Kostner, Jonathan Abdilla, Chris Scanlan Ramalingam Ramya, Ying Wang, Raymond Hung</i>	
Fluxless Vacuum Formic Acid Reflow of Indium Solder Thermal Interface Materials in Large Area BGA Packages	154
<i>Kyle Aserian, Ryan Mayberry, Andy Mackie, Phil Lehrer, David Heller, Xike Zhao, Fred Tarazi</i>	
Laser Assisted Bonding of InP Power Amplifier Chiplets on a 300 mm RF Si Interposer	162
<i>Damien Leech, Siddhartha Sinha, Hamideh Jafarpoorchekab, Nelson Pinho, Angel Uruena, Natalie Roels Lili Wang, Nazia Fathima, Ehsan Shafahian, Punith Mudigere Krishne Gowda, François Chancerel John Slabbekoorn, Akito Hiro, Luc van der Krabben, Alain Phommahaxay, Koen Kennes, Andy Miller Eric Beyne, Nadine Collaert, Xiao Sun</i>	
Pillar-Suspended Bridge (PSB); Fabrication Process Verification and Interconnect Design for 25-Micron Pitch Die-to-Die Interface	168
<i>Shinichi Arioka, Tanapun Srichanthamit, Koji Iwabu, Takashi Suzuki, Yoshiaki Aizawa, Yoichiro Kurita</i>	
Developments of Polymer Microwave Fiber Coupler in eWLB Package for Ultra-High-Speed Communication at D- and Y-Band	176
<i>Maciej Wojnowski, Ozan Yurduseven, Simon Kornprobst, Franz Xaver Engelsberger, Walter Hartner Parisa Aghdam, Sining An, Frida Strömbeck, Herbert Zirath</i>	
A Micro-3D Printed Helix Structure for sub-THz Antenna-on-Chip Modules	184
<i>Genaro Soto-Valle, Nikolas Roeske, Theodore W. Callis, Marvin Joshi, Manos M. Tentzeris</i>	
Differentially fed Sub-THz Broadband Antenna Arrays using Quartz Glass Cavity-backed Bonding Technology	190
<i>Alexander Gäbler, Uwe Maaß, Wojciech Partyka, Shoichiro Yamaguchi, Jungo Kondo, Kentaro Tani Naotake Okada, Masato Tokai, Makoto Iwai, Ndip Ivan</i>	
Advanced Scalable Modeling of High-Q Passives on a 300 mm RF Interposer Platform for mmWave and sub-THz Applications	196
<i>Côme Wallner, Dimitri Lederer, Xiao Sun</i>	
Signal and Power Integrity Co-Analysis of Chiplet(UCIe)-based GPU-HBM Interconnect for Reduced PHY Area	204
<i>Haeseok Suh, Jiwon Yoon, Youngsu Yoon, Junho Park, Hyunjun An, Junghyun Lee, Byeongmok Kim Eunji Seo, Keunwoo Kim, Jaegun Bae, Joungho Kim</i>	
Thermally Reconfigurable Split-Substrate Integrated Waveguide for Baseband and Broadband Signal Transmission	210
<i>Abdelrahman Omar, Md. Omar Faruk Noman, Soumitra Joy</i>	
Fully Integrated mmWave MIMO Radar with Compact Antenna-on-Package Design	217
<i>Aditya Jogalekar, Mohammad Vatankhah Varnoosfaderani, Marc Dewilde, Zachary Crawford, Cathy Chi Sunhwan Jang, Venkatesh Srinivasan</i>	
Predicting Long-Term Thermal Aging Behavior of Porous Sintered Layers via Hybrid Potts-Phase Field Model with Thermo-Mechanical Coupling	222
<i>Xiao Hu, Zichuan Li, Chao Gu, Junwei Chen, Jianlin Huang, René Poelma, Jiajie Fan, Willem D. Van Driel Guoqi Zhang</i>	

Influence of Design and Liner Material on Reliability of Through Glass Vias under Thermal Cycling: Numerical Modeling and Experimental Validation*	229
<i>Dalei Yang, Junbo Yang, Karthik Arun Deo, Kewei Shou, Yuhan Gao, Yi Deng, Weichen Zhao Yangyang Lai, Pengcheng Yin, Seungbae Park</i>	
Fracture Analysis for CoWoS Reliability Improvement	236
<i>Ming-Chih Yew, Chia-Kuei Hsu, Chien-Yu Wang, Chieh-Ming Chang, Po-Chen Lai, Kuo-Chin Chang Jia-Ming Yang, Chang-Fu Han, Jyun-Lin Wu, C.S. Chen, Jun He</i>	
Thermal Stress Reliability Optimization of TGV Density, Size, and Material Engineering for Glass based Advanced Substrate Technology	242
<i>Jaesung Kim, Yujeong Kim, Eunbi Ko, Jun Soo Chang, Soon Gil Lee, Jaesung Oh, Chang Bo Jung, Ken Lee Hyunwoo Nam, Tae-Ik Lee, MunSang You, Geonhee Lee</i>	
Thermal Storage Reliability Evaluation of Non-PFAS Potting Materials Used in Electronic Assemblies	250
<i>Yasitha Piyumal, Pradeep Lall, Ken Blecker</i>	
Enhancing Warpage Predictability by Considering Thermal Aging Shrinkage of EMC in Heterogeneous Integration Wafer Level Packaging	258
<i>Ji Lin, Alfred Yeo, Wang Yifan, Chan Kai Chong</i>	
High Temperature Shock Testing on QFN, Flip-Chip and Chip Resistor Solder Interconnects	265
<i>Max Häusler, Karsten Meier, Karlheinz Bock</i>	
Direct Bridge Multi-die (DBrM) Package: A Novel Silicon Bridge Chiplet Packaging Technology Using Die-Edge Gluing Technique for Chip Reconstitution	271
<i>Akihiro Horibe, Chinami Marushima, Takahito Watanabe, Atom Watanabe, Yasuharu Yamada Sayuri Kohara, Risa Miyazawa, Hiroyuki Mori, Divya Taneja, Isabel de Sousa</i>	
Scaling the EMIB-T Advanced Packaging Technology to Address the Future HPC/AI Demand	277
<i>Tarek Ibrahim, Zhiguo Qian, Jianyong Xie, Yidnekachew Mekonnen, Jung Kyu Han, Ali Lehaf Tchefor Ndikum, Siddarth Kumar, Jason Gamba, Kaladhar Radhakrishnan, Kemal Aygün, Rahul Manepalli</i>	
Large Reticle Size Advanced Packaging Selection Strategy Based on Warpage: FOCoS and FOCoS-B	283
<i>Wu-Lung Wang, Chung-Hang Lai, Wiwy Wudjud, Wei-Hong Lai, Hsin-Chih Shih, Chin-Li Kao Chih Yi Huang, Kai Jung Su, Hung Hsiang Cheng, Lihong Cao, Chen-Chao Wang, Chih-Pin Hung</i>	
Demonstration of an Optical Packaged Substrate with Embedded Silicon Photonic Transceiver for High Performance Chiplet Packaging	288
<i>Fumi Nakamura, Akihiro Noriki, Kenta Suzuki, Satoshi Suda, Haruhiko Kuwatsuka, Naoki Matsui Reona Motoji, Dan Maeda, Tomoya Sugita, Hiroki Yamamoto, Hirotaka Uemura, Takeru Amano</i>	
Process Integration Challenges in Heterogeneous Integration of XPU, HBM and Photonic Chiplets for AI/HPC Applications	293
<i>Lai Yee Chia, Tran Van Nhat Anh, San Sandra, Tai Chong Chai</i>	
Marvell custom HBM routing and signal integrity analysis	298
<i>Joshua F. Dillon, Ting Zheng, Arshiya Vohra, Kazin Blacklow, Eric Tremble, Wolfgang Sauter, Sid Allman</i>	
Package Architectures for Hyper Large Form-Factors for AI and HPC Segment	304
<i>Mohit Khurana, Sujit Sharan, Aditya Vaidya, Kemal Aygun, Kaladhar Radhakrishnan, Jianyong Xie Chinmay Potdar, Patrick Nardi, Sachin Deshmukh, Brandon Marin, Prasanna Raghavan, Satish Surana Shripad Gokhale, Nisha Ananthakrishnan</i>	

Ultra-Fine 1.4- μm Pitch Face-to-Back Chip-on-Wafer Cu–Cu Hybrid Bonding for the Chip-on-Wafer-on-Wafer Integration	312
<i>Itsuki Imanishi, Akihiro Urata, Masanori Chiyozono, Toru Osako, Kan Shimizu, Yoshihisa Kagawa</i>	
Process Optimization for Chip-to-Wafer Hybrid Bonding Using Inter-Die Gap Fill Integration Approach	318
<i>Mishra Dileep Kumar, Vasarla Nagendra Sekhar, Sasi Kumar Tippabhotla, Hipona Randy Tupaen Norhanani Jaafar, B.S.S. Chandra Rao, Daniel Ismael, Xie Ling, Ser Choong Chong Vempati Srinivasa Rao</i>	
Characterization of Bonding Behavior and Void Formation in Chip-on-Wafer Hybrid Bonding	326
<i>Zhao-Ze Jiang, Chih-Jing Hsu, Chen-Hung Lee, Che-Ming Hsu, Jen-Chieh Kao, Yung-I Yeh Alexis Angelo Garcia, Po Hsiang Wang</i>	
Inverse Hybrid Bonding at 5 μm Pitch for High-Density Heterogeneous Integration	331
<i>Madison Manley, Wanshu Zeng, Dipayan Pal, Ashita Victor, Danish Baig, Andrew C. Kummel Muhannad S. Bakir</i>	
Development of Particle Robust Micro-Scale Interconnect by Cured-Polymer and Solder (MICS) Technology Down to 3 μm Pitch	338
<i>Mitsuru Ooida, Akiyoshi Aoyagi, Mamoru Sasaki, Shunsuke Akatsuka, Ayumi Nakajima, Kai Takagi Toshihisa Nonaka</i>	
Initial Assessments of Fine Pitch Cu-Cu TCB for 3D Integration	343
<i>Vineeth Harish, Jui-Han Liu, Diana Cantini, Samuel Wang, Goutham Ezhilarasu, Anton Turpault Adeel Bajwa, Subramanian S. Iyer</i>	
Next-Generation Optical-Electrical Co-Design Interconnect Using Low-Temperature Hybrid Bonding Technology	350
<i>Lin-Chun Su, Jou-Yun Yeh, Yu-Lun Liu, Chun-Ta Li, Chien-Kang Hsiung, Yu-Tao Yang, Shang-Hsuan Wu Kazuaki Ebisawa, Makiko Irie, Chung-Jui Lee, You-Chia Chang, Kuan-Neng Chen</i>	
Enhancement of Thermal Conductivity of the Advanced Packaging Materials by Using BNNT	358
<i>Changho Kim, Hikaru Uchida, Yuka Yamashita, Junha Hwang, Duy Khoe Dinh, Min Seok Kwak, Ji-In Lee Hiroki Ito, Cheolwoo Kwak, Jaewoo Kim</i>	
AlN-based Chiplet Encapsulation: Enhancing Thermal Performance for High-density Heterogeneous Integration	364
<i>Ashita Victor, Dohyun Go, Hansol Lee, Diego Contreras Mora, Andrew C. Kummel, Muhannad S. Bakir</i>	
Interfacial reaction of In-Ag thermal interface materials with Ti/Ni/Ag backside chip metallization and its influence on thermal resistance	372
<i>Chun-En Lin, Polina Leger, Ke-Yen Ma, Anne Groth, Olaf Wittler, Thi Minh Anh Dao, Yu-Heng Hong Chun-Hao Chen</i>	
Development of High Thermal Conductivity Molding Materials for Automotive Flip Chip Packages	377
<i>Hungyuan Li, Masahiro Iwai, Jerry Wang, Fa-Chuan Chen, HL Chen, Bo-Kuan Yeh, Song J. M, Sean Kuo Koichiro Uchida</i>	
In-Situ Cure Monitoring of EMC by Fiber Bragg Grating and Dielectric Sensors with Molecular Dynamics Validation for Accurate Warpage Prediction	383
<i>Woo-Jin An, Jeong-Hyeon Baek, Woong-Kyoo Yoo, Jun-Seop Song, Ji-Hye Shim, Gyung-Hwan Oh Hak-Sung Kim</i>	

Anisotropic 0D–1D Hybrid Molding Compound for Low Warpage and Enhanced Thermal Management in Advanced Packages	390
<i>Young-Joon Lee, Woong-Ryeol Yu</i>	
Development of Negative Thermal Expansion Fillers for Next-Generation Advanced Semiconductor Encapsulation Materials	398
<i>Tetsuharu Yuge, Yutaro Tanaka, Kazuki Tsujikawa, Chie Matsunaga, Suresh Rao Nagendra Rao Akihiro Oohara, Haruki Koshitouge, Masahiro Yokoyama</i>	
Reliability Prediction Model for the Solder Joint Bridging Failure of Large-Body BGA Packages Under System-Level Heatsink Compression	403
<i>Hsueh-Ying Liu, Siao-Yu Chen, Tz-Cheng Chiu</i>	
Systematic Reliability Study of a Large Size 2.5D Package with RDL Interposer for AI Processor	411
<i>Richard Rao, Ivan Tan, Richard Graf, Tushar Chauhan, Dwayne R. Shirley, Theo Anemikos, Tim Hayes Susan Li, Kevin Caffey</i>	
The first report of Si Bridge type 2.5D package's reliability for Automotive Applications	418
<i>Tomoko Takahashi, Ken Imai, Ryota Morimoto, Mitsufumi Ishii, Yasuhiko Maki, Shiro Machida Shuichi Kariyazaki, Takuya Nakamura</i>	
Reliability of Multilayer Glass Core Packages With Polymer And Inorganic Through Glass Via (TGV) Liner And Fully Plated TGVs	426
<i>Meghna Narayanan, Pragna Bhaskar, Kaushik Godbole, Lakshmi Narasimha Vijay Kumar, Lila Dahal Durga Gajula, Kyoung-Sik Moon, Muhannad Bakir, Suresh K. Sitaraman, Mark Losego Mohanalingam Kathaperumal</i>	
Reliability of SAC PBGA Assemblies Using Constitutive and Failure Models Incorporating Damage Mechanics	432
<i>Golam Rakib Mazumder, Souvik Chakraborty, Mahub Alam Maruf, Omma Sumaiya, Jeffrey C. Suhling Pradeep Lall</i>	
Chip-Package-Board Interconnects Reliability Challenges and Solutions in Large Die Fine Pitch WLCSP	440
<i>Varun Thukral, Gaurav Sharma, Michiel Van Soestenbergen, Amar Mavinkurve, Nishant Lakhera Abdullah Fahim, Greta Terzariol</i>	
Predictive Reliability Modeling of Hybrid Bonding Through Warpage and Interfacial Defect Correlation	447
<i>Liton Kumar Biswas, Himanandhan R Kottur, Istiaq Firoz Shiam, Pavanbabu Arjunamahanthi, Neil Hubble Paul Handler, Victor Vilar, Dadi Setiadi, Charles Woychik, Navid Asadizanjani</i>	
Enabling 12+Gb/s HBM4E with EMIB-T Advanced Packaging Technology	455
<i>Yidnekachew Mekonnen, Jianyong Xie, Zhiguo Qian, Xenofon Konstantinou, Yunpeng Si, Yiran Cui Kemal Aygün, Kaladhar Radhakrishnan</i>	
Scalable Electroplated Cu and Co Metaconductor for Low Loss 112 to 400 Gbps Wired Communication Interconnects	461
<i>Saeyeong Jeon, Ariel David Cerpa, Yong-Kyu Yoon</i>	
Advanced SI/PI Interposer Design Solution Enabling High-Performance HBM4e at up to 12Gbps	466
<i>Taeyun Kim, Sungwook Moon, Seungki Nam, Kyoungseok Oh</i>	

Temperature and Yield-Aware Design of UCIe Die-to-Die Interconnects for Advanced Packaging	472
<i>Ram Krishna, Ashita Victor, Zhonghao Zhang, Atom Watanabe, Xu Chen, Muhannad S. Bakir Elyse Rosenbaum</i>	
Figures of Merit to Characterize the Signal Integrity Performance of Interposer Interconnect for High Bandwidth Memory (HBM)	480
<i>Taeil Bae, Jinwon Lee, Hyunggon Bae, Hyunsik Kim, Inchul Jeong, Hyungsoo Kim</i>	
Cross-Topology Transfer Learning Using Bayesian Optimization for Scalable Surrogate Modeling of 3D Packaging Structures	486
<i>Md Sultan Mahmud, Xianbo Yang, Priyank Kashyap, Madhavan Swaminathan</i>	
Analytical Approach to Statistical Modeling of Power Supply Induced Jitter	494
<i>Hyunjun An, Junghyun Lee, Haeseok Suh, Jiwon Yoon, Byeongmok Kim, Junho Park, Youngsu Yoon Jaegeun Bae, Joungho Kim</i>	
Accelerated Multi-Physics Simulation of Moisture-Induced Stress in Electronic Packages via Sequential Coupling	500
<i>Liangbiao Chen, SM Yeasin Habib, Xuejun Fan, Yong Liu</i>	
Micro/Nanostructural Stress Characterization for Advanced 3D Integration Technologies	506
<i>Tatsumasa Hiratsuka, Mario Gonzalez, Peng Zhao, Eric Beyne, Masaki Haneda, Shoji Kobayashi Yoshiya Hagimoto, Masashi Nakazawa</i>	
Mechanics-Based Sequential Fabrication Model of Glass-Core Packages with Embedded Chiplets in Redistribution Layers	512
<i>Alexander R. King, Hyunggyu Park, Muhannad Bakir, Suresh K. Sitaraman</i>	
A Study of Electromigration Failure Criteria and Contributing Damage Factors	520
<i>Choong-Un Kim, Harikrishnan Kumarasamy, Dong Seok Lee, Tae-Kyu Lee, Sylvester Ankamah-Kusi Yan Li</i>	
Experimental Studies Towards Better Understanding of RDL Microstructure and Built-Up Stresses for Reliable Glass-Enabled Advanced Packaging	526
<i>Chukwudi Okoro, Rajesh Vaddi, Mandakini Kanungo, Diego Prado, Robert Schaut</i>	
Mechanical Impact of Embedded Capacitor Array on Processor Module for High Performance Computing Applications	532
<i>Robert Darveaux, Richard Sheridan, Imran Khan, Maryam Rezaie</i>	
Experimental and Computational Fracture Strength Characterization at BEOL Structure Sharp Corners for Chip-Package Interaction Reliability Assessment	540
<i>Jehun Youn, Jonathan A. Whitby, Pei-En Chou, Ganesh Subbarayan</i>	
Process Development and Thermal Characterization of Micropillar Direct-to-Silicon Liquid Cooling Solution on CoWoS-R Platform	546
<i>Sing-Da Jiang, Chun-Yu Ou, Chi-Shiang Chiou, Yu-Sheng Tsai, Chang-Yi Tsai, Chuan-Chang Wu Tsun-Yen Wu, Ying-Ju Chen, Wen-Hsiung Lu, Tzong-Huann Yang, Ren-Yu Chang, Kathy Yan, Rick Lien Jun He</i>	
Toward Reliable and Thermally Robust BSPDN: A Dual-Path Design Based on BN–BN Bonding	553
<i>Chi Hsueh, Mu-Ping Hsu, Chun-Che Cheng, Jia-Rui Lin, Kuan-Neng Chen</i>	

System-Level Thermal Validation of 2.5D Packages in GPU Servers: Impact of TCB vs HCB HBM Platforms	558
<i>Woohyun Park, Youchang Na, Seongjin Hong, Yoko Tomo, Hae Jung Yu, Yanggyoo Jung, Gyungbum Kim Heeyoub Kang, Yeonghyeon Gim, Eduardo Hernandez Pacheco, Jaechoon Kim, Yun Seok Choi</i>	
High performance direct liquid jet impingement cooling on structured Silicon	565
<i>Herman Oprins, Georg Elsinger, Vladimir Cherman, Geert Van der Palas, Zsolt Tokei, Eric Beyne</i>	
Process Development of Two-Stacked Chips with a Backside Embedded Two-Phase Cooling Solution	572
<i>Xiaowu Zhang, Boon Long Lau, Huicheng Feng, Gongyue Tang, Ming Chinq Jong, Surya Bhattacharya Vempati Srinivasa Rao, B.S.S. Chandra Rao, Tran Van Nhat Anh</i>	
Diamond-on-Chip Integration for Enhanced Thermal Management and Warpage Control in 2.5D Chiplets Packaging	579
<i>Zeming Tao, Ningning Xu, Dongchen Fan, Jinbao Zhang, Yixiong Wu, Weiyi Lin, Rongbin Xu Dongxue Liang, Delong Qiu, Yi Zhong</i>	
Low Warpage Double Side RDL interconnection with Electrical Compensation for Panel Level Package	584
<i>Terry Wang, Cheng-Yueh Chang, Chien-Ming Tseng, Yu-Jhen Yang, Pei-Pei Cheng, Wendy Chou Hungyu Wu, Austin Cheng, Hsin-Yi Huang, Simon Zhong, Chi-Hua Huang, Kent Chen</i>	
Panel CMP Co-planarization of Heterogeneous Interfaces for Damascene Organic Interposers (L/S = 2/2 μm)	588
<i>Katsuaki To, Masashi Minami, Sadaaki Katoh</i>	
3D Integration of an SRAM chiplet in Fan-Out Embedded Bridge Platform Achieving Low Energy Read/Write	593
<i>Dany-Sebastien Ly-Gagnon, Li Chen, Dwight Lee, Max Wu, Jiajing Wang, Ping-Chen Liu, Ch Yang Chung-Ching Peng, Steven Lin, Bruce Xu, Chung Kang Cai</i>	
Influence of Metal Surface Characteristics on Auto Focus Reference Position and Pattern Fidelity in Fine-Pitch RDL Applications	599
<i>Jaehyuk Chang, Hyunseok Yang, Youmin Chang, Seokhun Choi, Kyung Chan Hwang, Chanjin Park Mingu Kang, Zhongchuan Zhang, Chang I Su, Wen Fu, CC Chuang, Yingchiao Wang</i>	
Study of SeWaRe Failure in a Glass-Core Substrate with Redistribution Layers	604
<i>Kaushik U. Godbole, Nirvan Patel Masini, Alexander King, YongWon Lee, Suresh K. Sitaraman</i>	
Low-cost process of organic RDL-based packaging platform enabling UCIe 32 GT/s link speed	612
<i>Donggyu Kim, Jun-Su Kim, Kwang Il Kim, Jun-Beom Kim, Yong-Gyu Jang, Yeon Ji Shin, Jae-Sung Lim Sangkyu Jang, Jin-Wook Jang, Sangyong Park, Seungho Lee, Jaeyoung Kim</i>	
FOWLP-Enabled 3D Package-Level Heterogeneous Integration with Advanced Heat Spreading Architecture for Next-Generation Mobile Device	618
<i>Kyung Don Mun, Jihwang Kim, Sangjin Baek, Wooyoung Kim, Bong-Soo Kim, Dahye Kim, Bongju Cho Se Hoon Jang, Jaechoon Kim, Suk Won Jang, Eun Young Lee, Dae-Woo Kim</i>	
Low-Loss Optical Interconnect Designs in Optimized Glass for Co-Packaged Optics	622
<i>Lars Brusberg, Jorge Holguin-Lerma, Matthew J. Dejneka, Lucas W. Yeary, Chad C. Terwilliger Betsy J. Johnson, Charisse Spier, Jonathan E. Walter, Katerina Rousseva, Sean M. Garner</i>	

Detachable Glass Waveguide Connector for Co-Packaged Optics on Silicon Photonics platform with <1.5 dB/Facet Passive Coupling and 280 mW Power Handling	626
<i>Arpan Dasgupta, Sean Garner, A.K.M. Zahidur Chowdhury, Takako Hirokawa, Rajesh Vaddi Brian Popielarski, Jasmeet Singh, Yusheng Bian, Kevin Eaton, Jae Kyu Cho, Yarong Lin, Geng Ni Keith Donegan, John Garant, Helen Wong, Robert Katz, Ryan Sporer, Michelle Zhang, Janet Tinkler Asli Sahin, Norman Robson, Jean-Baptiste Laloe, Kevin Dezfulian, Jean Trehella, Bob Mulfinger Ken Giewont, Ted Letavic, Koushik Ramachandran, Rick Carter, Vikas Gupta, Martin Spreemann Robert Lee, Chuan Che Wang, Tim Grygiel, Andreas Matiss</i>	
Laser Cleaning of Optical Couplers on Photonic Integrated Circuits	631
<i>Jean-Philippe Bérubé, Alexandre Douaud, Feng Liang, Loïc Arias, Philippe Lassonde, Philippe Gagnon Simon Duval, François Légaré, Louis-Rafaël Robichaud</i>	
Development of a High-Efficiency, Wide-Temperature-Range Optical Coupling Structure for CPO Modules	636
<i>Shuhei Sudo, Megumi Oishi, Misa Takahashi, Shogo Enomoto, Kono Sasaki, Tomoyuki Akahoshi</i>	
High-Density Polymer Waveguide Integration on Glass Substrate for CPO	642
<i>Takuya Kitainui, Yujiro Saito, Naoki Fukuda, Kenichi Ogawa</i>	
Low-Loss Polymer Waveguide Device for Fiber-to-Chip and Chip-to-Chip Connection	647
<i>Kai Yokoyama, Haruka Nakajima, Takaaki Ishigure</i>	
Integrated Assembly Process For Pluggable Fiber Connector For Co-Packaged Optics	651
<i>Jelena Pesic, Lily Yuan, Joy Zhan, Shuhe Li, Digvijay Raorane, Dehua Xiao, Masha Gorchichko Suresh Pothukuchi, Subal Sahni, Ankur Aggarwal</i>	
Selective Layer Transfer to Enable Fine-Grain Mixed Front-End Devices with Monolithic Interconnects	658
<i>Tushar Talukdar, Nordeen Paul, Thomas L. Sounart, Mohammadreza Yaghoobi, Abhishek A. Sharma Andrey Vyatskikh, Brandon Rawlings, Clifford J. Engel, Lei Jiang, Felipe Bedoya, Siyan Dong Charles El Helou, Mudit Bhargava, Adel A. Elsherbini, Shawna M. Liff, Aleksandar Aleksov, Myung-Hee Na</i>	
First Demonstration of microBump-based Massive Orthogonal Stacking Assembly IC (MOSAIC) Cube for SoC-DRAM Direct Stacking	664
<i>Hung-Chih Huang, Yuki Mitarai, Masaya Kawano, Takafumi Fukushima, Mototsugu Hamada Atsutake Kosuge</i>	
Electroplated Cu-Diamond Composite Thermal Vias for Interposer-Level Heat Management in 2.5D/3D Packages	671
<i>Ye Yang, James Chien, Tiwei Wei</i>	
Optical Engine (OE) Integration Challenges for Next-Generation CPO on Networking and HPC Application	679
<i>Mike Tsai, Ming Han Zhuang, Shane Lin, Steven Lin, Michael Fu, Bruce Xu, Yih Jenn Jiang, Don Son Jiang</i>	
High Power System Scaling Using Double-Sided Connection in Embedded Substrate	684
<i>Sheng Li, Chu Jie Yang, Min Lung Huang, Yue Nung Lin, Jen Kuang Fang</i>	
Top-Side Silicon Capacitor for Co-Optimized Thermal and Power Delivery in FoWLP for Mobile SoCs	689
<i>Kyojin Hwang, Woobin Jung, Youngsang Cho, Jisoo Hwang, Heeseok Lee, Daehyun Kim, Seung Wook Yoon</i>	
High-Thermal-Conductivity (1.0 W/(m•K)) Dry-Film Solder Resist at 20 μm : Compatible with Standard Process Flow and Steady-State Thermal Validation	694
<i>Takumi Suzuki, Kohei Kitagawa, Ryohei Nojima, Fumitaka Kato, Daichi Okamoto, Zihao Lin Kyoung-Sik Moon, Mohanalingam Kathaperumal, Ching-Ping Wong</i>	

SUBSTRATE-CLOAK: A MEMS-Enabled Reconfigurable Obfuscation Framework for Secure Substrate Interconnects	700
<i>Himanandhan Reddy Kottur, Pavanbabu Arjunamahanthi, M. Shafkat M. Khan, Pragyna Abhishek Titty Liam S. Hayes, Liton Kumar Biswas, Katayoon Yahyaei, Md Shah Imran Shovon, Bo Liu, Istiaq Firoz Shiam Michael Delany, Joshua Hihath, Navid Asadizanjani</i>	
Cryogenic Via-last TSVs for 2.5D Qubit Chip Implementation Demonstrating DC–20 GHz Signal Transmission at Millikelvin Temperatures	708
<i>Misato Taguchi, Takuji Miki</i>	
Demonstration of Superconducting-material-filled TSV on Cryogenic Packaging Platform	712
<i>Hongyu Li, B. N. Jaafar, Ya-Ching Tseng, Tran Van Nhat Anh, Yong Chyn Ng</i>	
Fabrication and Experimental Characterization of Embedded Multi-Terminal Capacitors With Ultra-Low Parasitics for Integrated Vertical Power Delivery	717
<i>Ramin Rahimzadeh Khorasani, Xingchen Li, Mohammad Al-Juwahri, Mahin Ahamed, Wisnu Murti Taedong Kim, Madhavan Swaminathan</i>	
Hidden in Traffic: Timing Leakage in Heterogeneous Integrated Processors	725
<i>Abir Akib, Sanjay Jay Rekhi, Kostas Amberiadis, Ankur Srivastava</i>	
Surface-Mounted Conformal Adhesive Electrodes for Impedance-Based Crack Detection in Composite Materials	733
<i>Riadh Al-Haidari, Babatunde Falola, Mousa Al-Zanina, Stephen Gonya, Mark Poliks Andrew Stemmermann, Daniel Balder</i>	
AI-Driven Inverse Design and Vision Fusion Framework for Automated Signal Integrity Optimization of Organic RDL Interposers	740
<i>Minsun Cho, Taeheon Lee, Jiho Yu, Dayeong Kim, Sungyoep Jung</i>	
Multiscale Mechanical Characterization of Hybrid-Bonding Copper: From Instrumented Indentation to AFM	748
<i>Nicolas A. Alderete, Paresh D. Daharwal, Yvonne B. Gerbig, Gheorghe Stan, Cristian V. Ciobanu</i>	
Nanoindentation-Based Analysis of Wafer-to-Wafer Bond Strength Using Cohesive Zone Modeling and Machine Learning	756
<i>Yusuf Burak Ozdemir, Oguzhan Orkut Okudur, Kris Vanstreels, Mario Gonzalez, Clement Merckling Eric Beyne</i>	
Effects of the Chip Geometry and Bonding Initiation Point on Bonding Distortion in Die-to-Wafer Hybrid Bonding	762
<i>Takaaki Hirano, Tatsumasa Hiratsuka, Taichi Yamada, Koki Onshi, Shoji Kobayashi, Yoshiya Hagimoto Masashi Nakazawa</i>	
First Demonstration of 450nm Pitch Cu-Cu Hybrid Bonding with 98% Yield Across 20M Interconnects for Ultra-Dense 3D Integration	769
<i>Ying Trickett, Roger Quon, Yoocham Jeon, Amit Prakash, Raghav Sreenivasan, Raghuvier Patlolla Joan Chung, Ju Seon Goo, Sang Jin Kim, Norman Tam, Shashank Sharma, Jeremiah Hebding Siddarth Krishnan, Michael Chudzik, Barabara Weis, David Goldberger</i>	
System-Level Thermal Characterization of Hybrid Cu Bonded HBM on 2.5D Advanced Packaging	774
<i>Seongjin Hong, Haejung Yu, Hyuek Jae Lee, Younglyong Kim, Jin Hyuk Chang, Mingyu Kang, Sangho Shin Eunhee Jung, Youchang Na, Yooseok Jeong, Hyung Joon Jun, Seonghyun Park, Woohyun Park Yeonghyeon Gim, Jaechoon Kim, Yun Seok Choi</i>	

Near-IR Excited Upconversion Nanoparticles for Optical Wafer-to-Wafer Bonding	781
<i>Aparnaa Iyer, Eren Özmen, Mohanalingam Kathaperumal, Mark D. Losego, C.-P. Wong</i>	
Fine-pitch Cu-Cu Hybrid Bonding Using Electroless-deposited (111) Nanotwinned Cu	787
<i>Wei Choong Lee, Po-Shao Shih, I-En Chen, Cheng-Yan Yang, Yu-Hsiang Lu, Yun-Ching Hung</i> <i>Yung-Sheng Lin, Chen-Chao Wang, Chih-Pin Hung, C. Robert Kao</i>	
Glass Core Substrates – Next Generation Advanced Packaging Platform for AI and HPC	792
<i>Srinivas Pietambaram, Tarek Ibrahim, Nicholas Psaila, Hiroki Tanaka, Vinith Bejugam, Dhruva Pattadar</i> <i>Praveen Sreeramagiri, Manohar Konchady, Jeff Kaplan, Izabela Murtagh, Changhua Liu, Rahul Manepalli</i>	
Optimization of Glass Substrate CTE for Warpage Control and Solder Joint Reliability in Large HPC Packages	798
<i>Pengcheng Yin, Junbo Yang, Yangyang Lai, Karthik Arun Deo, Kewei Shou, Dalei Yang, Seungbae Park</i>	
First Demonstration of Low-loss W-/D-Band Vertical Interconnects on Multi-stacked Ceramic-Glass Substrate for 6G Antenna-in-Package Modules	803
<i>Chenhao Hu, Genaro Soto Valle Angulo, Kyoung-Sik Moon, Manos M. Tentzeris</i>	
Development of Long-term Reliability for Glass Core Substrates with Build-up layers	809
<i>Koji Fujimoto, Satoru Kuramochi</i>	
Scaling Interconnect Density with Silicon-Core-Substrate Nano-Integrated VIA Technology	814
<i>Seann Ayers, Steven Verhaverbeke, Han-Wen Chen, Suresh Ramalingam</i>	
InfinityBoard A Panel-Level Glass-Core Packaging Platform for Ultra-Fine RDL and Vertical Interconnect Integration	819
<i>Roland Rettenmeier, Laurent Nicolet, Michael Kothe, Udo Kirsch, Christian Schmid, Sven Seren</i> <i>Thomas Widmann, Christian Buchner, Dian Zhang</i>	
Hybrid bonding surface roughness characterization: A RHEED approach with high speed and atomic scale (sub-nm) sensitivity at wafer level	823
<i>Weichang Lin, Nicholas Polomoff, Roy Yu, Katsuyuki Sakuma, James Lu, Toh-Ming Lu, Gwo-Ching Wang</i>	
Signal and Power Integrity of Organic, Silicon, and Hybrid Interposer in HPC Chiplet-Based System	831
<i>Ming-Hung Wu, Yaotsu Chen, Yi-Chin Tsai, Po-Yuan Wei, Liang-Kai Chen, ChungHsuan Wu</i> <i>Chun-Hong Chen, Sheng-Fan Yang</i>	
Novel Metrology For Experimentally Visualizing Cu-Cu Bonding Induced Thermal Stress	836
<i>Jie Li, Keyu Wang, Shuhang Lyu, Tiwei Wei</i>	
Vertical Interconnects Characterization for 448 Gbps/lane Co-Packaged Optics using Double-Sided Probing Method	844
<i>Jiaqi Wu, Sajay Bhuvanendran Nair Gourikutty, Teck Guan Lim, Surya Bhattacharya</i>	
Photonic Interconnects in Glass Core for AI Data Center Applications	850
<i>Md Rayid Hasan Mojumder, Ziyu Guo, Ning Li, Madhavan Swaminathan</i>	
Photonic Fabric™ Interconnect for a Scale-up Network Solution in Accelerated Computing	856
<i>Dan Oh, Ankur Aggarwal, Suresh Pothukuchi, Jelena Pesic, Subal Sahni, Parmanand Mishra</i> <i>Ganesh Balamurugan, Trung Diep, Phil Winterbottom, David Lazovsky</i>	
Advanced 3D Packaging Optics Engine with Integrated Micro-VCSEL Array for Ultra-High Bandwidth Optical Interconnect	862
<i>Yuk-Tong Cheng, Murphy Chengkang Lee, Tzu-Hung Lin, Wang Shi Yu, Chih-Hsiang Ho, Jr-Hau He</i>	

Fabrication and transfer of fine pitch RDL using Si temporary carrier combined with IR laser release approach	867
<i>François Chanceler, Gilberto Casillas, John Slabbekoorn, Peter Urban, Simon Halas, Mario Graml Steven Brems, Koen Kennes, Arnita Podpod, Thomas Uhrmann, Markus Wimplinger, Alain Phommahaxay Zsolt Tokei, Eric Beyne</i>	
IR Laser Debond Process Modeling	872
<i>Thomas Sounart, Henning Braunsch, Paul Nordeen, Tushar Talukdar, Md M Hasan, Karan Prabhakar</i>	
Novel Organic Temporary Bonding Material for High-Temperature Semiconductor Processing Applications	880
<i>Taichi Kikkawa, Yutaka Hisamune, Satoshi Inada, Yuzo Nakamura</i>	
Study of Sn Damascene Process for Novel Fine Pitch Micro-Bump Formation and Bonding	887
<i>Kosuke Yamashita, John Slabbekoorn, Jaber Derakhshandeh, Eric Turner, Kazuki Tomota, Haiying Zhou</i>	
Thin cleanable organic laser release layer with ultralow laser transmittance below 360 nm wavelength for TBDB	895
<i>Hanlin Chen, Loyde Braidlow, Amit Kumar, Alice Guerrero, Elliott Fitch, Deborah Blumenshine Luna Liang, Christopher Bakker, Arthur Southard</i>	
Novel Temporary Bonding Film and Debonding Method Adapted for the Fabrication Process of Large Size Panel Packages	901
<i>Motohiro Negishi, Yuta Akasu, Koji Yukimatsu, Emi Miyazawa, Tetsuya Enomoto, Tomohiro Ohkubo Saeko Ogawa, Masanori Natsukawa, Tomohiko Kotake</i>	
Electroplated Indium Micro-Bumps: Toward Scalable Low Temperature Ultra-Fine Pitch Interconnects	907
<i>Maria-Luisa Calvo-Muñoz, Yacoub Sahouane, Erwan Mekadem-Belaid, Mathilde Gottardi Abdelhak Hassaine, Marie Maubert, Laurence Gabette, Laurence Andreutti, Catherine Pellisier Alain Gueugnot, Chafik Mhamdi, Thierry Mourier</i>	
ENEPES as an Effective Surface Finish for Enhancing Electromigration Reliability in Solder Joints	915
<i>Mai Yokota, Tsuyoshi Maeda, Katsuhisa Tanabe</i>	
Direct to Silicon Microfluidic Cooling for Datacenters	920
<i>M. Baris Dogruoz, Sashikanth Majety, Venkata Chivukula, Cam Turner, Bharath Ramakrishnan Husam Alissa, Srikanth Bharadwaj, Camille Couturier, Malik Fahrni, Yann Meier, Remco Van Erp Samuel Higginbotham</i>	
Enabling Reliability Testing of Solder Interconnects Under Extreme Current	924
<i>Choong-Un Kim, Jorge Mendoza, Dong Seok Lee, Harikrishnan Kumarasamy, Sylvester Ankamah-Kusi Qiao Chen, Tae-Kyu Lee, Patrick Thompson</i>	
Cu-core solder interconnect mechanical shear strength under high current density	929
<i>Tae-Kyu Lee, Yujin Park, Adnan Mahmud, Gnyaneshwar Ramakrishna, Young-Woo Lee, Hui-Joong Kim Jae-Yeol Son, Seul-Gi Lee</i>	
Evolution and Correlation of Microstructure and Mechanical Properties in Aged SAC/LTS Hybrid Solder Joints	937
<i>Mahbub Alam Maruf, Souvik Chakraborty, Jeffrey C. Suhling, Pradeep Lall</i>	
Time-Resolved 3D X-ray Imaging of Electromigration Void Evolution in 2.5D Package	946
<i>Junbo Yang, Stephen Cain, Yuhao Gao, Dalei Yang, Karthik Deo, Yi Deng, Kewei Shou, Seungbae Park</i>	

Effects of Plating Current Density on Electrochemical Reliability of RDL: In-Situ Electrochemical Migration Testing and Time-to-Failure Prediction	954
<i>Ho-Jin Lee, Jeong-Hyeon Baek, Hae-Su Ahn, Tae-Hoon Kim, Ji-Hye Shim, Hyoc-Min Youn, Hakgee Jung Hak-Sung Kim</i>	
Deep Coordination Graph-Based Reinforcement Learning for Multi-Domain PDN Optimization	960
<i>Junho Park, Seonguk Choi, Inyoung Choi, Gwantaek Lee, Jiwon Yoon, Junghyun Lee, Youngsu Yoon Byeongmok Kim, Jaegeun Bae, Chulhee Cho, Jinwook Song, Joungho Kim</i>	
Design Methodology and Power Integrity Analysis of Staggered Current Pattern for Voltage Drop Mitigation in High-Power Multi-Core HPC system	968
<i>Hyunwoong Kim, Sungwook Moon, Jungil Son, Chaewon Baek, Seungki Nam</i>	
Dynamic Power Management Methodology for Distributed Vertical Power Delivery in High-Performance Computing Systems	973
<i>Sriharini Krishnakumar, Inna Partin-Vaisband</i>	
Neural Surrogates for Fast Signal and Power Integrity Co-Simulation and Co-design of Chiplets Integration	979
<i>En-Xiao Liu, Richard Xian-Ke Gao, Zaifeng Yang, Jun Liu, Dingjie Lu, Mihai D. Rotaru, Dutta Rahul N. Sridhar</i>	
Design Space Exploration of Chiplet and Interposer PDNs for 2.5D AI Systems	985
<i>Seungmin Woo, Taehoon Kim, Madison Manley, Muhannad S. Bakir</i>	
Fast Signal and Power Integrity Analysis Algorithm of UCIe-Based High-Speed Links with Transistor-Level Equalizers	991
<i>Yi Zhou, Lewei Tang, Tahsin Shameem, Bobi Shi, José E. Schutt-Ainé</i>	
PINS: Power Integrity-Aware Power Delivery Network Synthesis in Interposer-Based Advanced Packaging	997
<i>Tzu-Han Hsu, Iris Hui-Ru Jiang</i>	
Physics-Constrained Multi-Agent Automation for Design-for-Reliability: From Literature to Auditable Knowledge and Experimental Design	1005
<i>Jialong Liang, Jiajie Fan, Guoqi Zhang, Willem D. van Driel</i>	
Physics-Informed Neural Network Approach for Fast Prediction of Temperature Distribution and Hot Spots in Co-Packaged Optics	1013
<i>Sohrab Sheikh Sofla, Madhavan Swaminathan, Gordon Chang, Meiju Lu, William Chen, C.P. Hung C. M. Hung, Yu-Tao Yang, Chinq-Shiun Chiu</i>	
StressScore: Evaluating AI Predicted Stress Contours in Advanced Packaging With Contrastive Learning	1021
<i>Kart Leong Lim, Thanmaya Bharadwaj Puvvada</i>	
AI-Driven Surrogate Modeling and Uncertainty Quantification for Active Power Cycling in Power Electronics Packages	1030
<i>Dharshan Barkur, Przemyslaw Jakub Gromala, Karsten Meier, Karlheinz Bock</i>	
In-situ anomaly detection for power MOSFET's degradation based on unsupervised LSTM-Autoencoder	1038
<i>Shaojian Xie, Mesfin Seid Ibrahim, Jialong Liang, Hiu Hung Lee, Chang Lu, Guoqi Zhang, Jiajie Fan</i>	

Cross-domain Integrated Digital Twin for Heterogeneous Integrated CPUs	1046
<i>Mumtahina Islam Sukanya, Aniket Bharamgonda, Abhijit Dasgupta, Ankur Srivastava</i>	
A Physics-Informed AI Platform for Warpage Prediction and SMT Feasibility in Versatile 2.5D Packaging	1054
<i>Kewei Shou, Junbo Yang, Karthik Arun Deo, Dalei Yang, Pengcheng Yin, Yangyang Lai, Weichen Zhao Yi Deng, Yuhan Gao, Seungbae Park</i>	
Advancing Interconnect Performance and Reliability with Innovations in 3D Photonic Integration Packaging and Fiber Coupling	1061
<i>Sufi Rizwan Ahmed, Sandeep Sane, Reza Baghdadi, Bradley Snyder, Suresh Jayaraman</i>	
Photonic Fabric™ Chiplets for Co-Packaged Optics in AI Data Centers	1065
<i>Suresh Pothukuchi, Rekha Govindaraj, Jared Farr, Sagar Dubey, Digvijay Raorane, Ankur Aggarwal Dan Oh</i>	
V-groove Based Edge Coupling Enabled by Optical Glass Coupler Attach for Co-packaged Optics	1071
<i>Zhou Yang, Fan Fan, Timothy A Gosselin, Ryan D Mcqueen, Pratyasha Mohapatra, Anita Dey Anurag Tripathi, Shan Zhong, Bohan Shan, Jesus S Nieto Pescador, Corey Logston, Nicholas Psaila</i>	
Power Distribution Network (PDN) Design and Analysis for Multi-Stack 3D Heterogeneous Integrated High Bandwidth Memory (3D-HI-HBM) Module	1077
<i>Jiwon Yoon, Haeseok Suh, Eunji Seo, Junghyun Lee, Hyunjun An, Youngsu Yoon, Chaemin Yang Jaegeun Bae, Hyunseo Uhm, Joungho Kim</i>	
Thermal-Aware Power Integrity Analysis of Embedded Integrated Voltage Regulator (IVR) in Interposer for 2.5D High-Power HPC	1082
<i>Hyunwoong Kim, Sungwook Moon, Jungil Son, Jinho Kim, Seungki Nam</i>	
Multi-physics Design Methodology for Enlarged Chiplets Interconnections in Advanced Packaging	1087
<i>Yung-Sheng Lin, Chih-Yi Huang, Teck-Chong Lee, Smith Chen, Po-Chih Pan, Fu-Chen Chu Tsung-Tang Tsai, Chung-Hung Lai, Wei-Hong Lai, Chin-Li Kao, Chen-Chao Wang, Chih-Pin Hung</i>	
Topology-Driven Organic Interposer Design for RDL Layer Reduction in Automotive UCle-A 2.5D Chiplet Packages	1093
<i>Shuuichi Kariyazaki, Hiroki Shibuya, Tatsuki Tsukuda</i>	
Novel Process Integration for Highly Reliable and Manufacturable 0.4-μm-pitch 50 M Cu-Cu Connections	1101
<i>Yukako Ikegami, Ken Arano, Masanori Chiyozone, Kengo Kotoo, Kan Shimizu, Yoshihisa Kagawa</i>	
Reducing Wafer-to-Wafer Bonding Misalignment to Enable 140nm Pitch Hybrid Bonding	1108
<i>Christopher Netzband, Andrew Tuchman, Joshua Greklek, Shinichi Tan, Yuki Taniguichi, Nathan Ip Atsushi Nagata, Sayantan Das, Brittany Hedrick, Hirokazu Aizawa, Ilseok Son, Angelique Raley</i>	
Wafer-to-Wafer Hybrid Bonding Technology with 200nm Interconnect Pitch	1113
<i>Stefaan Van Huylenbroeck, Lieve Bogaerts, Koen D'havé, Soon Aik Chew, Hung-Chieh Tsai, Serena Iacovo Sven Dewilde, Shuo Kang, Joeri De Vos, Zsolt Tókei, Eric Beyne</i>	
Robust Wafer-to-Wafer Cu Direct Bonding Process for Multi-Stacked CMOS Directly Bonded to Array (CBA) Technology in Future 3D Flash Memory	1119
<i>Masayoshi Tagami, Hiroaki Ashidate, Mitsuhiko Noda, Ryo Tanaka, Mamoru Watanabe, Ryuta Mizumoto Genki Sawada, Yoshiharu Ono, Tomoyuki Takeishi, Katsuyuki Sekine</i>	

Process Integration for 300-nm-Pitch Hybrid Bonding with SiCN: 50nm Bonding Overlay, Fine-Grain Cu Metallurgy, and Reliability Assessment	1126
<i>Kai Ma, Nikolaos Bekiaris, Jingting Nicole Chen, Jing Xu, Huixiong Dai, Jakob Haimberger</i>	
<i>David Goldberger, Gernot Probst, Thomas Uhrmann, Markus Wimplinger</i>	
Synchrotron-Based Characterization of Cu/SiCN Pretreatment for Hybrid Bonding via Ozone/Ethylene Radical Activation	1133
<i>Bungo Tanaka, Mariappan Murugesan, Soichiro Motoda, Tetsuya Nishiguchi, Yuma Okadome</i>	
<i>Tetsu Tanaka, Takafumi Fukushima</i>	
Nanostructured Porous Cu for Ultralow-Temperature Direct Bonding	1138
<i>Su-Ching Hsiao, Wei-Lan Chiu, Shih-Cheng Yu, Hsiang-Hung Chang, Chin-Hung Wang, Wei-Chung Lo</i>	
<i>Shih-Chieh Chang, Shih-Chieh Chang</i>	
Non-Destructive Characterization of Laser-Induced Molecular Modification in Glass for Selective Etching to fabricate Through-Glass Vias (TGV) in Advanced Packaging	1143
<i>Mruga Panse, Kyoung-Sik Moon, Mohanalingam Kathaperumal, Stefan Janssen, Youngho Suh</i>	
<i>Myungjoo Park, Jehhoon Bhang, Ching-Ping Wong</i>	
Crack-free through-hole drilling of 400 μ m-thick aluminosilicate glass by direct laser processing	1148
<i>Toshio Otsu, Tsubasa Endo, Hiroharu Tamaru, Yohei Kobayashi</i>	
Development of Low-Modulus Primer "Cbla" to Prevent SeWaRe in Glass-Core Substrates	1153
<i>Daichi Kobayashi, Marie Ohuchi, Satoshi Takayasu, Yuzuru Kobayashi, Masahiro Miyasaka</i>	
<i>Kosuke Urashima, Tomohiko Kotake</i>	
Novel Photosensitive Material with Low Shrinkage and Low Dielectric properties for High-Density RDL in Glass Packaging	1158
<i>Ritsuya Kawasaki, Kazuya Nakashima, Yu-Chieh Lin, Hyunggyu Park, Kyoung-Sik Moon</i>	
<i>Mohanalingam Kathaperumal, Ching-Ping Wong</i>	
Digital Lithography Patterning of Novel Dry Film Resists for High Aspect Ratio Cu Pillar Applications on 310 $\times$ 310mm ² Panel Substrates	1163
<i>Ksenija Varga, Lisa Berger, Tobias Zenger, Hajime Furutani, Masayuki Kishino</i>	
Low-Warpage Multilayer RDL Technology Using Thin Dry Film Dielectric with Reduced Curing Shrinkage and Dry-Etched Ultrafine Via	1168
<i>Yusuke Naka, Tadahiko Hanada, Osamu Okada, Takafumi Fukushima, Hiroyuki Hashimoto</i>	
<i>Yasuhiro Morikawa, Fumito Ootake, Masahiro Sawa, Yasuhiro Ogo, Yoichiro Kurita</i>	
Inkjet-Printed Photo-Imageable Dielectric for Large-area Uniform Coating and High-Resolution Patterning in Advanced Packaging	1175
<i>Myung Joo Park, Beom-Soo Kim, Youngho Suh, Wanhyuk Chang, Kee Joon Kim, Minyoung Lim</i>	
<i>Hyunsoon Lim, Wooram Oh</i>	
First Demonstration of a 200 $\times$ 200 mm ² Glass Substrate for Large Area Packages	1181
<i>Jaewon Lee, Hyunggyu Park, Seungwoo Cha, Jinsun Yoo, Srujan Penta, Tushar Krishna</i>	
<i>Muhannad S. Bakir</i>	
Technical study of RDL in advanced package using ultra-low Df film-type photo imageable dielectric	1189
<i>Keigo Yamaguchi, Yuta Yamakawa, Megumi Tanaka, Masayuki Miura, Daisuke Ando, Naoki Sato</i>	
<i>Takuya Komine, Eiichi Hayashi, Takashi Kariya</i>	

Dry-Film-Only Process for Panel-Level 2.xD Packaging Enabling 2/2- μ m Line/Space RDL and 5- μ m Microvias	1196
<i>Ryo Kikuta, Masashi Minami, Ryosuke Kimura, Sachiko Matsushita, Takeshi Yamada, Masahiko Suzuki Sadaaki Katoh</i>	
Tether-Free Micro-Transfer-Printing of Si-based Micro-Inductors: Demonstration of on-Glass and in-Silicon Integration for PowerSoC applications	1204
<i>Amit Tanwar, Muhammet Genc, Liang Ye, Rayan Bajwa, Somnath Pal, Iurii Efimenkov, Ranajit Sai Cian O'Mathuna, Brian Corbett, Sambuddha Khan</i>	
Advanced Manufacturing Solutions for Large Form Factor Patch on Interposer (PoINT) Scaling	1211
<i>Andrew Carlson, Qichang Wang, Khalid Abdelaziz, Fatemeh Rahimi, Tingting Gao, Xiao Lu</i>	
Game-Changing Nanosolder Technology: Self-Assembling Adhesives for Sub-10 μ m Ultra-Fine Interconnects	1216
<i>Jin Woo Huh, Seol Kim, Tae-Wan Kim, Hyeong-Bin Park, Changhoon Sim, Hak-Sung Kim, Kyungsub Lee</i>	
Additively Manufactured Foldable Interconnects for 4D/Morphing Origami-Inspired mm-Wave Arrays	1223
<i>Hani Al Jamal, Manos M. Tentzeris</i>	
Rapid Additive Manufacturing of Multi-Layered RDL and Interconnects Enabled by Hybrid Metal-Polymer	1230
<i>Natalya K Crawford, Jaden Wang, Daria Holoman, Jarrett Bealer, Seungjun Lee, James Garcia Zachariah Page, Michael Cullinan</i>	
High-Precision Wafer-Level Bonding in Thin-3D: A Moiré Pattern and Deep-Learning Alignment Approach	1235
<i>Chen-Chia Chang, Shie-Ping Chang, TingRay Chung, Nien-Chih Lin, Po-Jung Sung, Chih-Chao Yang Kung-Neng Chen</i>	
Metallization Challenges: Conformable Deposition for Super High-Aspect Ratio (> 100) Fine TGV and Cu Pillar Embedment for 1-mm-Deep Fat TGV	1242
<i>Chang Liu, Kiyoharu Mori, Jiayi Shen, Bungo Tanaka, Hidenori Miyauchi, Murugesan Mariappan Tetsu Tanaka, Takafumi Fukushima</i>	
Glass-Stacked Interposers with Microdispensed Silver Nanopaste for Low-Temperature 3D Interconnection	1250
<i>Sam LeBlanc, Bryce Gray, Josue Fuentes, Lance Sookdeo, Jason Benoit, Eduardo Rojas, Kenneth Church</i>	
Advancing Sustainable Die-attach Technologies with Filled Bio-Sourced Epoxy Resin Systems	1255
<i>Frederic A. Banville, Catherine Marsan-Loyer, Josée Labrecque, Saria Berger, Cloe Druillolle Benjamin Busseniers, Katherine Pilger, Valerie Oberson, David Danovitch, David Gendron, Serge Ecoffey</i>	
Mitigating the Thermal Bottleneck in Advanced BEOL Interconnects	1263
<i>Xinyue Chang, Herman Oprins, Melina Lofrano, Bjorn Vermeersch, Zsolt Tokei, Seongho Park Ingrid De Wolf</i>	
Multiscale Thermal Simulator development for high resolution Hot Spot analysis	1270
<i>Hiroyuki Ryoson, Shinji Sugatani, Takayuki Ohba</i>	
Experimental Characterization of Thermal Transport in Cu/Sn–Diamond Microbumps	1276
<i>Keyu Wang, Zhengwei Chen, Devang Tavkari, Shusmitha Kyatam, Jie Li, Noah Opendo Joana Catarina Mendes, Miguel A. Neto, Amy M. Marconnet, Tiwei Wei</i>	

Flash Boiling of Methanol in Silicon Microchannel Thermal Dissipation Unit for Thermal Management	1284
<i>Naarendharan Meenakshi Sundaram, Zachary Wong, Priyanth Elango, Subramanian S. Iyer Timothy S. Fisher</i>	
Advanced Thermal Solutions for Thin 3D: AlN 3D Heat Dissipation Network	1292
<i>Shang-Lun Pai, Shie-Ping Chang, Chen-Chai Chang, Po-Jung Sung, Nine-Chih Lin, Chih-Chao Yang Kyle Huang, Gary Huang, Jeremy Lin, Kuan-Neng Chen</i>	
High-Fidelity Package-Level Conjugate Thermal-Flow Simulation for a Memory-on-Logic 3D System with Embedded Liquid-Cooling	1298
<i>Yujui Lin, Hongchi Liu, Luke Gyubin Min, Walker Turner, John Wilson, Tahir Cader, Mehdi Asheghi C. Thomas Gray, Kenneth E Goodson</i>	
Identification of Local Dryout Signatures in Two-Phase Microchannel Heat Sinks Using a Multi-Chip Module Thermal Test Vehicle	1306
<i>Rishav Roy, Yang Liu, Sarwesh N. Parbat, David J. Apigo, Manohar Bongarala, Syed Faisal, Todd Salamon Mark Cappuzzo, Ting-Chen Hu, Rose Kopf, Ed Sutter, Nagesh Basavanhally, Alaric Tate, Bob Farah Rick Papazian, Mark Earnshaw</i>	
Die-To-Wafer Hybrid Bonding Technology down to 1 μm pitch for Multi-Die Stacking Integration	1313
<i>Melissa Najem, Agathe Lerat, Carine Ladner, Loic Sanchez, Julien Diaz, Renan Bouis, Jérôme Dechamp Antonio Roman, Myriam Assous, Damien Saint-Patrice, Lilian Masarotto, Stéphane Nicolas</i>	
Enabling Scalable Die-to-Wafer Hybrid Bonding Through Die Distortion Correction and Grid Measurement	1321
<i>Alex Hsu, Imene Jadli, Anne Jourdain, Samuel Suhard, Etienne De Poortere, Andy Miller, Koen Kennes Victor Blanco, Amir-Hossein Tamaddon, Eric Beyne</i>	
Reworkable Die-to-Wafer Hybrid Bonding Process	1327
<i>Rajan Gangadharan, Dominik Suwito, Thomas Workman, Cyprian Uzoh, Justin Chen, Pawel Mrozek Arianna Avellan, Suhail Sadiq, Laura Mirkarimi</i>	
Enabling Beyond-16-Layer 3D Stacking with Ultra-Thin Die Hybrid Bonding with Integrated Bonder	1335
<i>Guan Huei See, Shin-Puu Jeng, Arvind Sundarrajan, Loke Yuen Wong, Patrick Lim, Xiao Dong Chen Santosh Kumar Rath, Xing Zhao, Prayudi Lianto, Ashok Muthukumaran, Michael Chudzik</i>	
Low distortion fusion bonding using pneumatically warped wafers	1339
<i>Utkarsh Jain, Koen D'havé, Philipp Schmidt, Damien Leech, Serena Iacovo, Philippe Muller Dennis Bumuller, Thomas Schmidt, Koen Kennes, Steven Brems, Eric Beyne</i>	
Wafer Bonder and Lithography Co-Optimization for Sub-5nm Post-Bonding Overlay in Backside Power Delivery Architectures	1347
<i>Andrew Tuchman, Leon van Dijk, Christopher Netzband, Sheldon Meyers, Sayantan Das, Niyam Haque Manav Tyagi, Lienneke Kusters, Nathan Ip, Ilseok Son, Angelique Raley</i>	
Enabling Ultra Low Temperature Hybrid Bonding for D2W Scaling	1352
<i>Veronica Strong, Jeff Bielefeld, Arijit Koley, Felipe Bedoya, Richard Vreeland, Michael Njuki, Siyan Dong Haris Niazi, Brandon Rawlings, Trianggono Widodo, Satyajit Walwadkar, Pilin Liu, Saurabh Chauhan Farhad Daneshvar, Tushar Talukdar, Carlos Chavez, Aleks Aleksov</i>	
Fluxless Thermo-Compression Bonding of 4X Reticle Die Stack	1358
<i>Kartik Srinivasan, Mine Kaya, Danis Nugroho, Nicholas Cool, Niranjana Parab, Karthik Visvanathan Shan Zhong</i>	

Simplified Fluxless Bonding via Ultraviolet Activation: Enabling High-Reliability Fine-Pitch Interconnections	1363
<i>You-Gwon Kim, Dong-Hoon Yoo, Hyeong-Bin Park, Seungchul Shin, Dongsuk Kang, Hak-Sung Kim</i>	
Fluxless TCB with in-situ Atmospheric Pressure Plasma Surface Treatment Enabling 25-micron Pitch Solder Micro-Bumps for 3D Integration	1370
<i>Mohammed Alhend, Luke Darling, Roy Yu, Neng Liu, Ming Li, Zetao Ma, Kai Ming Yeung, Le Cheng Katsuyuki Sakuma</i>	
Processing and cold testing of superconducting and thermal conducting TSVs	1377
<i>Qian Yang, Jaber Derakhshandeh, Anish Dangol, A. M. Vadiraj, Anne Jourdain, Geraldine Jamieson Karl Ceulemans, Rami Chukka, Koen Kennes</i>	
BBCube 2.5D: A Bumpless 2.5D Integration Technology Enabling High-Density Inter-Chiplet Interconnection Using Waffle-Wafer and Via-Last TSVs	1383
<i>Norio Chujo, Shinji Sugatani, Koji Sakui, Masao Taguchi, Hiroyuki Ryoson, Takayuki Ohba</i>	
TSV Stress Prediction via Machine Learning Based on EBSD Grain Microstructure	1388
<i>Zhenliang Pan, Jie Li, Shuhang Lyu, Rui Yan, Jaden Li, Tiwei Wei</i>	
Chemically Tailored Cu-Electroplating and Contactless Isostatic Annealing of 1-mm-Thick Full Glass Wafer Cu Through-Glass-Vias	1396
<i>Murugesan Mariappan, Kiyoharu Mori, Hiroyuki Hashimoto, Takamichi Miyazaki, Masahiro Sawa Jinta Nampo, Takafumi Fukushima</i>	
Optical RDL Interposer Technology using Polymeric Hybrid Bonding and Waveguide for Integrated CPO	1403
<i>Toshihiko Katayama, Kazuki Inoue, Kyohei Hayashi, Motoya Kaneta, Yuma Tanaka, Ryota Kinoshita Takafumi Fukushima</i>	
Multi-Mode Polymer Waveguides for Co-Packaged Optics	1410
<i>Ross Johnson, Yaming Jiang, Rui Zhang, James Ryley, Barbara Roeske, Henry Cain, Nancy Tassi John Allen, Zhou Lu, Elizabeth Brundage, Masaki Kondoh, Michael Gallagher</i>	
Layer Transfer of Epitaxial Ru by Metal-Metal Bonding: Towards Single-Crystal Interconnects	1415
<i>Christoph Adelman, François Chancerel, Jean-Philippe Soulié, Steven Brems, Peter Kerepesi Michael Dornetshumer, Florian Medl, Tobias Wernicke, Christoph Flötgen, Markus Wimplinger Zsolt Tókei, Seongho Park</i>	
Reflectivity-Tunable Localized Epitaxy for Multi-Tier Monolithic 3D ICs	1422
<i>Ching-Lin Chen, Yu-Chun Chen, Yu-Ming Pan, Chiao-Yen Wang, Chih-Chao Yang, Chang-Hong Shen Chenming Hu, Kuan-Neng Chen</i>	
Siloxane Elastomer-Based Zero-CTE Prepreg Substrates for Foldable FPCB and Stress-free Advanced Semiconductor Packaging	1427
<i>Hyungshin Kweon, SungHun Park, Byung Jo Um, Seung-Mo Kang, Byeong-Soo Bae</i>	
Characterization of Solderless Connection by Laser Welding and Its Application on Power Module	1433
<i>Ming-Hung Chen, Yi-Chun Chou, Chun-Yi Cheng, Ren-Jieh Kao, Yun-I Yeh</i>	
Extreme High-Temperature Evaluation of Printed Platinum Materials for Aerospace Applications	1438
<i>Abdullah S. Obeidat, W T Alshaibani, Erik Busse, Olya Noruz Shamsian, Masoud Mahjouri-Samani Stephen Gonya, Felipe Pavinatto, Mark D. Poliks</i>	

3D Analysis of Hybrid Copper Bonding through X-ray Photon-Counting Nano-CT Imaging	1445
<i>Till Dreier, Darius Rückert, Spyridon Gkoumas, Julius Hållstedt</i>	
Microchannel-Embedded 3D-Printed Ceramic Substrates for Liquid-Cooled Power Module Packaging	1452
<i>Haksoon Jung, Seongju Kim, Nahyeon Kim, Seungjun Chung, Jimin Kwon</i>	
3D Stacked GPU Architecture with Ultra-Thin 3D DRAM Dies and Voltage Regulators Embedded into Glass Substrate	1457
<i>Pin-Jun Chen, Janak Sharda, Po-Kai Hsu, Min Gyu Park, Sung Kyu Lim, Muhannad Bakir, Shimeng Yu</i>	
Efficiency Meets Fidelity: A Computational Paradigm for 3D X-ray Imaging of HBM Packages	1464
<i>Yang Yu, Jie Wang, Richard Chang, Ser Choong Chong, Eva Wai Leong Ching, Ramanpreet Singh Pahwa Xulei Yang</i>	
Chemical Vapor Deposition (CVD) Diamond-filled Through Vias for Enhanced Vertical Heat Transport in 3D Heterogeneous Integration	1472
<i>Ye Yang, Joana Catarina Mendes, Miguel A. Neto, Gil Cabral, Tiwei Wei</i>	
Wafer-Level Integrated 1200 V SiC MOSFET Package with Room-Temperature Wafer Bonding and Embedded Microfluidic Cooling	1479
<i>Jiajing Nie, Jiuyang Tang, Hao Guan, Xinyue Wang, Tao Jiang, Junran Zhang, Guoqi Zhang, Guangyin Lei Fengwen Mu, Pan Liu</i>	
An Innovative Automated Tracing Method for Defect Identification in Advanced FOCoS-Bridge Package	1485
<i>Cheng-Hsin Liu, Yi-Sheng Lin, Yu-Jen Chang, Yu-Jing Cheng, Yu-Ting Lin, Chen-Chao Wang Chin-Pin Hung, Fan-Ju Hsiao</i>	
Understanding the Effect of Bismuth and Surface Finish on Thermo-mechanical Reliability of Flip-Chip BGA Solder joints	1490
<i>Varun Thukral, Eleni Tsepi, Lara Reboucas, Pieter Gommers, Sharan Kishore, Abdullah Fahim, C.S. Foong</i>	
A Real-Time Resistance Monitoring Architecture for Prognostics and Health Management of Electronic Packages	1496
<i>Shaheen Pouya, Mostafa Rahgouy, Sa'd Hamasha, Jeffrey C. Suhling</i>	
Automotive Reliability of Micro-Cu Pillar Bumps for 2.5D Chiplet Integration	1504
<i>Koichi Ando, Yoshiaki Yamada, Hideaki Tsuchiya, Hiroki Shibuya</i>	
Enhanced Fault Localization Approach for Advanced Packaging with RDL Interconnection Nano-Defects	1510
<i>Yi-Sheng Lin, Wiwy Wudjud, Cheng-Hsin Liu, Yu-Ting Lin, Yu-Jing Cheng, Chen-Chao Wang Chin-Pin Hung, Lihong Cao</i>	
Dependence of Leakage Current Characteristics on Bonding Dielectrics in Fine-Pitch Hybrid Cu Bonding	1515
<i>Sohye Cho, Hyeonmin Lee, Sungjae Choi, Seokho Kim, Hojin Lee, Seunghun Lee, Young-Chang Joo</i>	
Reliability Enhancement of FC-QFN Packages Using Cu Pillar Bump with PSPI and Buffer RDL for ULK	1521
<i>Daehyun Kim, Yongju Lee, Soomoon Park, Kwangho Lee, Kisu Joo, Heeseok Lee, Seungwook Yoon</i>	
Reliability Evaluation of 10-Second Cu/Polymer Hybrid Bonding for Next-Generation 3D Integration	1526
<i>Tzu-Yu Chen, Yu-Lun Liu, Kazuaki Ebisawa, Makiko Irie, Jia-Rui Lin, Ya-Chien Chuang, Hsiao-Wei Yeh Satoshi Fujimura, Yuan-Chiu Huang, Kuan-Neng Chen</i>	

Printing Path Optimization for Reliability Enhancement in Direct-Writing Flexible Circuits	1531
<i>Yusen Nie, Luke McGinnis, Rui Chen</i>	
Multilayer Additive Circuit Process-Performance-Reliability Interactions in Dynamic Flexing of Wearable Applications	1538
<i>Shriram Kulkarni, Yasitha Piyumal, Pradeep Lall</i>	
Interfacial Fracture Characterization Using Wedge Testing of Electroless Plated Films on Additively Manufactured Conductive Polymers	1546
<i>Joshua Corbin, Sharmin Jahan, Nathan Lazarus, Nicholas J. Ginga</i>	
Mechanical Simulation of Stretchable Sensors Conforming to Non-Euclidean Surfaces Using ANSYS LS-DYNA	1553
<i>Sara G. Lieberman, Riadh Al-Haidari, Mark D. Poliks, Felipe Pavinatto, Gilad Zorn</i>	
Warpage Prediction After Compression Molding Using Cure-dependent Viscoelastic Properties	1561
<i>Sukrut Prashant Phansalkar, Bongtae Han</i>	
Warpage Prediction of PCB in Multi-Laminating Processes Considering Cure Shrinkage and Anisotropic Visco-Elastic Properties of Prepreg Core	1569
<i>Sanjay Kumar, Woong-Kyoo Yoo, Jaesung Kim, Chae-Young Ahn, Jinwoong Kim, Chan Hyuk Park Hak-Sung Kim</i>	
Coupled Thermo-Mechanical-Chemical Simulation Framework for Warpage and Stress Analysis in Post Mold Cure	1575
<i>Kyeong-Bin Kim, Eun-Ho Lee</i>	
Experimental Studies of Assembly Material Creep Behaviors and The Impact to Package Warpage	1583
<i>Ziyin Lin, Yanbiao Chu, Mohammad Kabiri, Cih Cheng</i>	
Layout-Driven FEM for Thermal and Thermo-Mechanical Analysis of MPGA and BGA packages	1588
<i>Hyunggyun Noh, Woongkee Kim, Youngbong Kim, Sanggon Lee</i>	
In-Situ Observation and Modeling of Crack Velocity at Wafer-to-Wafer Bonding Interface	1596
<i>Kyeong-Bin Kim, Haeri Kim, Wonyeop Jeong, Ju-Yong Shin, Youngsu Yun, Jong Han Shin, Jiho Kang Eun-Ho Lee</i>	
A Novel and Cost-Effective Evaluation Strategy for Solder Joints Reliability for HPC and AI Applications	1603
<i>Peng Su, Leif Hutchinson, Omar Ahmed, Bernard Glasauer</i>	
Methodology for Root Cause Analysis of 3D Multi-Chip Module Severely Damaged in Data Center Application	1608
<i>Charles Odegard, Al Griffin, Kasey Adams, James McElrath, Venkat Kalyanaraman, Anagha Kulkarni</i>	
Finite Element Analysis Based Methodology to Predict Electrical Parameter Shifts due to Mechanical Stress	1612
<i>Siva P. Gurrum, Hung-Yun Lin, Alexander Gamez, Li Jen Choi, Benjamin Amey, Ann Concannon</i>	
Thermal Behavior of Hybrid Bonding Interfaces in Advanced Packaging Technologies	1617
<i>Bijan Nili, Charles El Helou, Hadi Zandavi, Siyan Dong, Aaron Schmidt, Yi Shi, Tushar Talukdar Lynn Chen, Xavier Brun, Aleksandar Aleksov</i>	

FEA-Integrated 3PB And BOR Testing For Fracture Strength Characterization Of Ultra-thin Dies: Effects Of Thickness, Surface Conditions, And Anisotropy	1623
<i>Jun-Seop Song, Sang-Il Kim, Gyu-Won Kim, Woong-Kyoo Yoo, Jong-Woon Yoo, Sang-Hoon Ko Hak-Sung Kim</i>	
Simulation-Based Corrective Strategies for Warpage Behavior in Automotive Electronic Assemblies	1629
<i>Chih-Yang Weng, Shen-Yu Yang, Chao-Chieh Chan, Chang-Chun Lee, Shih-Wei Huang</i>	
Stress Analysis of Cu-Cu Hybrid Bonding Interface Under Thermal Loading	1635
<i>Haozhong Wang, Bingxu Ma, Peijiang Liu, Wanchun Tian, Hongtao Chen, Xiaofeng Yang</i>	
Thermal Characterization and Power Dissipation Enhancement of Hybrid-Bonded Chip Stack	1641
<i>Yong Han, Boon Long Lau, Lin Ji, Gongyue Tang</i>	
Orientation-Engineered AlN for Lateral Heat Spreading and Hotspot Management in 2.5D/3.5D ASICs on the Cloud AI Platform	1646
<i>Jun-Nan Liu, Tzu-Tai Chiu, Kuan-Chung Fu, Wan-Yun Lee, Chao-Chih Chen, Wen-Pin Hsieh Chih-Huang Lai</i>	
AI Head-Node Socket Interconnect Yield, Warpage, and Functionality	1651
<i>Steven Klein, Amit Abraham, Alexander Huettis, Taylor Rawlings, Eric Erike, Jacob Schichtel Sugadh Bakare, Srinivasa Aravamudhan, Renn Chan Ooi, Prasanna Raghavan</i>	
Liquid Metal Cooling for High-Power Electronics Driven by Magnetohydrodynamic Effect	1656
<i>Huicheng Feng, Bin He, Gongyue Tang, Xiaowu Zhang, Wei Kin Tan</i>	
A Holistic Study of Board Level Reliability of CoWoS-R Advanced Packaging on OCP Accelerator Modules	1664
<i>Sing-Da Jiang, Jing-An Huang, Chi-Shiang Chiou, Shih-Wei Liu, Tsun-Yen Wu, Ying-Ju Chen, Kathy Yan Rick Lien, Jun He</i>	
Controlling the Reaction Pathway to Tune Packaging Epoxy Properties	1670
<i>Polette Centellas, Ran Tao, Andrew Korovich, Alexander K. Landauer, Amanda Forster Siena Iavarone-Garza, Dante Ribeiro, Huong Giang Nguyen, Jan Obrzut, Stian Romberg, Christopher Soles</i>	
Influence of copper pad surface finish on electromigration performance of high-reliability SAC-based hybrid fine-pitched BGA solder joints	1677
<i>Karthik Arun Deo, Junbo Yang, Yangyang Lai, Dalei Yang, Kewei Shou, Weichen Zhao, Yi Deng Pengcheng Yin, Yuhan Gao, S B Park</i>	
Demonstration of Two-Phase Jet Impingement Cooling with Phase Separation Membrane using Water on High-Power AI GPU	1684
<i>Yunchun Yang, Sidharth Rajeev, Harish Kumar Lattupalli, Ketan Yogi, Srikanth Rangarajan Bahgat Sammakia, Tiwei Wei</i>	
Enhancing In-Package Thermal Management of 3D V-NAND Flash Memory Using Under-Periphery Thermal Pins (UPTPs) and Materials-and-Structure Co-Design	1691
<i>Eun Pyo Hong, Jung Su Yoon, Ho Beom Han, Suk-Kang Sung, Sang Won Yoon</i>	
Reliability Characteristics Of Through Glass Vias With Polymer Liners	1696
<i>Meghna Narayanan, Loic Constantin, Marvin Bernt, Poulomi Mukherjee, Sarah Wozny, Muhannad Bakir Mark D. Losego, Mohanalingam Kathaperumal</i>	

A Thermodynamic Continuum Framework for Electromagnetic–Mechanical Dissipation in Superconducting Qubit Systems	1701
<i>Sung-Hyun Oh, J Cha, Y Chong, Eun-Ho Lee</i>	
Experimental and Simulation-Based Assessment of Die Attach and Solder Mask Material Influence on Substrate Trace Cracking in BGA Packages	1707
<i>Chu-Chung Stephen Lee, Jasmine Lim, Ryan Zhang, Hy Liu, Hazika Hannah Samsol Bahri, Sharan Kishore Abdulla Fahim, Jetse De Witte, TuAnh Tran</i>	
Impact of Microstructure and Current Management on Electromigration Reliability in BGA Solder Joints for High-Performance Computing	1715
<i>Andrea Molina Moreno, Junyoung Bang, Miftahul Nabila, Kaitlyn Munoz, Tengfei Jiang Nicholas G. Rudawski, Omar Ahmed, Peng Su, Leif Hutchinson, Valery Kugel, Bernard Glasauer</i>	
Multiphysics Phase-Field Modeling of IMC Evolution and Reliability in Cu/Sn Fine-Pitch Interconnects	1721
<i>Haohan Guo, Shubhra Bansal</i>	
Assembly and Reliability Characterization of Glass-Cored Substrate Package for AI/HPC Applications	1728
<i>JoonYoung Choi, YoungJoo Choi, Nokibul Islam</i>	
Rapid Prediction of Effective Orthotropic Elastic Properties for 2.5D Chiplet Packaging RDL	1733
<i>Dingjie Lu, Jun Liu, Wenzu Zhuang, Richard Xian-Ke Gao, Enxiao Liu, Mihai D. Rotaru, Dutta Rahul N. Sridhar</i>	
Effect of Bi Concentration on the Creep Behavior and Reliability of Mixed SAC-LTS Solder Joints	1738
<i>Souvik Chakraborty, Mahbub Alam Maruf, Golam Rakib Mazumder, Jeffrey C. Suhling, Pradeep Lall</i>	
Modeling and Simulation of Se-Wa-Re Failure in Glass Core Substrates	1746
<i>Eduardo Barros de Moraes, Stanislav Sikulskyi, Robert Schaut</i>	
Heterogeneous Integration of Compound Infrared Focal Plane Arrays (FPAs) and Silicon Read-Out Integrated Circuits (ROICs) Using Laser-Assisted Bonding at a 15µm-Pitch	1752
<i>Gaeun Lee, Yong-Sung Eom, Gwang-Mun Choi, Jungho Shin, Ki-Seok Jang, Chanmi Lee, Jin-Hyuk Oh Seong-Cheol Kim, Mi-Ri Yoon, Sang Jun Lee, Dayoung Kim, Jungwon Yoon, Kwang-Seong Choi, Jiho Joo Hak-Sung Kim</i>	
Design and Optimization of 2-mm Staggered RDL Interposer Channels for UCIe 3.0 up to 64 GT/s	1758
<i>Hong Seok Kim, Youngeun Na, Yeon Ji Shin, Soo Jeong Kim, Jinsik Kim, Woojin Lee, Jae-Sung Lim Sang Yeul Yeum, Jayden Donghyun Kim</i>	
System-Level Framework for Co-Optimizing Electromigration and Voltage Drop in High-Power Packages	1765
<i>Jungil Son, Sungwook Moon, Hyunwoong Kim, Seungki Nam</i>	
Channel-Adaptive Generative Learning for Diverse Equalizer Design Space Exploration in High-Speed Links	1770
<i>Junghyun Lee, Hyunjun An, Jiwon Yoon, Haeseok Suh, Junho Park, Youngsu Yoon, Byeongmok Kim Jaegeun Bae, Inyoung Choi, Hyunseo Uhm, Eunji Seo, Joungho Kim</i>	
A Fully Printed Flexible Electrochemical DNA Sensor with 3D Printed Microfluidics for SoP Lab-on-Chip Applications	1778
<i>Theodore W. Callis, Manos M. Tentzeris</i>	

Damascene Fine Pitch RDL Process Development of 1.0 μ m CD for Line/Space using High-NA i-Line Scanner	1783
<i>Lili Wang, Natalie Roels, Kosuke Yamashita, Emile Schockaert, Carine Gerets, Denis Dochain Nancy Heylen, Kazuki Tomota, Tomoki Matsuda, Murat Pak</i>	
PALTO: Physics-Informed Active Learning for Tri-Gate FinFET Design Optimization for Vertical Power Delivery	1787
<i>Ayoub Sadeghi, Leonid Popryho, Inna Partin-Vaisband</i>	
Low-Loss Polymer Waveguides Based Architecture for Co-packaged Optics	1795
<i>Aparnaa Iyer, Sai Saravanan Ambi Venkataramanan, Pragna Bhaskar, Ethan Shackelford Janagama D. Goud, Yusuke Uraoka, Maki Tanaka, Atsushi Yamaguchi, Hirotaka Akiyama Tomo Muguruma, Tom Shin, C.-P. Wong, Muhannad Bakir, Mohanalingam Kathaperumal</i>	
Laser Assisted Transfer (LAT) of Coupon of III-V Epitaxial Layer on Silicon Photonics devices	1801
<i>Takenori Fujiwara, Junpei Oniki, Yukari Jo, Daichi Miyazaki, Takumi Ikehara, Haruka Fujishige Yuichiro Tsuda, Tatsuya Okada, Yoshiyuki Arai, James O'Callaghan, Peter O'Brien</i>	
Real-Time Lock-in Thermography and X-Ray CT for Early Failure Detection in Large-Size Packages	1806
<i>Yuji Inui, Donchoru Kan, Masaki Takahashi, Motoo Aoyama, Sojiro Isomura, Nao Matsuo, Sadaaki Katoh</i>	
3D-Printed Coaxial-Fed Patch-Antenna-Embedded Substrates for 5G Antenna-In-Package Applications	1811
<i>Kyungsun Kim, Haksoon Jung, Nahyeon Kim, Yongwoo Lee, Yunsik Park, Jimin Kwon</i>	
High-Bandwidth UC1e 2.0 Routing on Fine-Line Organic RDL with Enhanced Signal and Power Integrity for Scalable 64-Bit Multi-Chiplet Integration	1816
<i>Amit Kumar, Jitesh Shah, Nandakumar R.</i>	
Ultra-High Optical Power ELSFP Modules for CPO SiPh-Based Transceivers	1822
<i>Tetsuya Matsuyama, Kohei Umeta, Taketsugu Sawamura, Yuki Shiroishi, Hideyuki Nasu</i>	
IR-Drop Analysis of Power Delivery Networks in 3D Stacked Dies Using Face-to-Face and Face-to-Back Integration	1827
<i>Taehoon Kim, Seungmin Woo, Madison Manley, Muhannad S. Bakir</i>	
Monolithic Passive Low-Loss Fiber Coupling to Photonic Glass Core Substrates using Ion-Exchanged Waveguides and SLE-Fabricated V-Grooves	1833
<i>Maurice L. Haffner, Tom Chojne, Julian Schwietering, Hashem Al-Shami, Ulrike Ganesh</i>	
Electrical Design Guidance of Chiplet Interface Channels to Achieve 2634 GB/s/mm Die Edge Bandwidth	1837
<i>Jiwoon Moon, Jonghyeon Lee, Yuchul Jung, Yeji Kim, Kyungho Park, Youngwoo Kim</i>	
Multi-channel and multi-scale Optical Performance for a Detachable Edge-Coupling Connector with a Glass Coupler and Expanded Beam in CPO	1842
<i>Zhichao Zhang, Yalong Gu, Dekang Chen, Fan Fan, Feifei Cheng, Nicholas Psaila, Benjamin Taylor Duong Kumar Abhishek Singh, Kemal Aygün, Ravi V. Mahajan</i>	
Interface Enhancement Method for Silver-Sintered Flexible Strain Sensors Toward Improved Reliability and Sensitivity	1849
<i>Jiayu Ge, Letao Bian, Xinyue Wang, Guoqi Zhang, Pan Liu</i>	
Multi-Agent Reinforcement Learning Driven Package PDN Design Automation	1855
<i>Haran Manoharan, Chulsoon Hwang</i>	

Inverse Design for Ion-Exchanged Waveguides in Photonic Glass Core Substrates	1860
<i>Tom Chojne, Victor Doroshenko, Boris Bergues, Marc Schartmann, Julian Schwietering, Maurice Haffner Ulrike Ganesh</i>	
2.5D and Vertical Integration for Real-time Co-Optimization of Voltage Regulation and Power Gating in HPC Systems	1867
<i>Salma Abdelzaher, Inna Partin-Vaisband</i>	
A Metrology Development Platform for Digital Image Correlation-Based Measurement of Thermal Expansion and Cure Shrinkage in Epoxies	1875
<i>Alexander K. Landauer</i>	
3D Heterogenous Integration Packaging of 5G RF Systems using Additive Electronics	1881
<i>WT Alshaibani, Abdullah S. Obeidat, Riadh Al-Haidari, Zhi Dou, SG Lieberman, Shivantha Gunathilake Yoga Viswanathan, Stephen Gonya, Jason Case, Joseph Iannotti, Felipe Pavinatto, Mark D. Poliks</i>	
Optical Multi-Chip Interconnect Bridge (OMIB) Interposer Demonstration to Enable High-density Photonic Interconnects for High-Performance Computing Applications	1888
<i>Digvijay Raorane, Ankur Aggarwal, Suresh Pothukuchi, Saket Chadda</i>	
Additively Manufactured Interdigitated Capacitor for High Temperature Applications	1893
<i>Erik Busse, Mousa Al-Zanina, Abdullah Obeidat, Emuobosan Enakerakpo, WT Alshaibani, Stephen Gonya Matthew Erdtmann, Adrian Pyke, Mark D. Poliks</i>	
A Switchable Longitudinal & Shear BLS Microscope for Comprehensive Modulus Imaging of Semiconductor Packaging Materials	1900
<i>Andrew J. Gayle, Sebastian Engmann, Ran Tao, Andrew G. Korovich, Polette Centellas, Yvonne B. Gerbig Christopher L. Soles, Chris A. Michaels</i>	
Ultra High Resolution Micro-LED Display Enablement at 300mm Using W2W Hybrid Bonding for AI and AR Applications	1908
<i>Raghav Sreenivasan, Abhishek Bhat, Jason Appell, Sangwoo Lim</i>	
Low-Temperature Ultrathin Al ₂ O ₃ -SiO ₂ Direct Bonding: Development and Optimization for Heterogeneous Integration of All-Optical Neuromorphic Chips	1912
<i>Albert Augustino Anthony, Sajay Bhuvanendran Nair Gourikutty, Eva Leong Ching Wai, Ser Choong Chong</i>	
Piezo-Magnetostrictive Transducer-Powered Wireless Implanted Sensors for Monitoring Hemodynamics	1918
<i>Veeru Jaiswal, Reshmi Banerjee, Ghaleb Al-Duhni, Mohammad Mohtasim Hamid Pial, Okeoma Arinze Angelique Dominguez, Geraldine Pineda Andrade, Markondeya Raj Pulugurtha</i>	
High-Efficiency 2 by 1 Antipodal Vivaldi Array on Ultra-thin PTFE for sub-6 GHz 5G: Cricut-Based Rapid Prototyping and Characterization	1923
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Modeling and Optimization of 2-Stage Power Delivery Systems for High-Performance, Large-Area Packages	1930
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BEM-Based Characterization of a D-Band On-Chip Patch Antenna Array	1938
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A Design-Space Exploration of Active Interposer Architectures for Long-Reach Signaling in Large-Area Advanced Packages	1942
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Language-Model Interfaces for SerDes Design Optimization: Comparing Prompt-Based and Agentic Approaches	1947
<i>Nirjhor Rouf, Priyank Kashyap, Soumyadeep Chatterjee, Sounak Dutta, Chris Cheng, Paul D. Franzon</i>	
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Electromigration Resistance of Fine-Pitch Copper Lines: Comparison of Fine-Grained, Nanotwinned, and Standard Structures	1960
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Design of UCle-A x64 Chiplets Integration for 16-36 GT/s Using Organic Interposer	1965
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Unit Level Die-to-die Attach with Low Thermal Input Thermo-compression Bonding towards Co-packaged Optics Applications	1971
<i>Liban Jibril, Anita Dey, Jesus Nieto Pescador, Madhu Krishna Murthy, Sungmin Han, Niranjan Parab Anurag Tripathi, Timothy Gosselin, Shan Zhong</i>	
Novel Microbump Structure of Direct Solder Bumping on Seed Layer with Barrier Functionality (SoSBF)	1977
<i>Yusuke Tanaka, Keiichiro Hattori, Yuji Ohba, Aya Kurokawa, Toshiki Furutani, Takashi Kariya</i>	
Fine-Pitch Cu/Polymer Hybrid Bonding using Excimer Laser Damascene Process	1983
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Simultaneous Surface Reduction and Self-Passivation via Ar-CH ₄ Plasma for Cu Hybrid Bonding	1993
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Influences of Bonding Misalignment on Copper Bulge Out in Wafer-to-Wafer Hybrid Bonding	1997
<i>Ryohei Kojima, Yuriko Yamano, Kengo Kotoo, Taichi Yamada, Naoki Komai, Suguru Saito Yoshiya Hagimoto</i>	
Laser-Assisted Bonding with h-BN Filled Non-Conductive Film for Fine-Pitch Semiconductor Packaging	2002
<i>Seong-Cheol Kim, Jiho Joo, Yong-Sung Eom, Gwang-Mun Choi, Jungho Shin, Ki-Seok Jang, Jin-Hyuk Oh Chanmi Lee, Gaeun Lee, Miri Yoon, Seung-Yoon Lee, Kwang-Seong Choi</i>	
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Methodology for Fine Line Strength in Fan-Out Architectures	2014
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Contamination-Controlled Pre-Assembly for High-Density Die-to-Wafer Hybrid Bonding	2019
<i>Fabiana Lie Tanaka, Marie Sano, Kenta Hayama, Jun Maeda, Tomoko Iwatsubo, Takashi Ouchi Tsuyoshi Nakayama, Shinji Ishitani, Naoya Hirota, Fumihiro Inoue</i>	
Hierarchical 3D-Vertically staking with Multi-layer and Stacking with Novel Structure by Transferrable Cu/polymer Hybrid Bonding and 3D-Vertically Stacking For High speed Digital Applications	2025
<i>Ou-Hsiang Lee, Yu-Ping Chan, Wei-Lan Chiu, Hsiang-Hung Chang, Chia-Wen Chiang, Jr-Wei Peng Meng-Hsuan Chen, Kuan-Neng Chen, Jia-Rui Lin, Liang-Cyuan Chang, Jia-Wen Fan, Da-Cheng Chien Tsung-Yu OuYang, Chin-Hung Wang, Kuan-Neng Chen, Wei-Chung Lo, Chia-Hsin Lee, Chung-An Tan Shih-Chieh Chang</i>	
Integration and Characterization of Two Connection Schemes for Backside Power Delivery Network	2032
<i>Peng Zhao, Liesbeth Witters, Michele Stucchi, Vladimir Cherman, Melina Lofrano, Rami Chukka Kevin Vandersmissen, Farid Sebai, Bart Kenens, Jan Willem Maes, Joeri De Vos, Gerald Beyer, Zsolt Tokei Eric Beyne</i>	
Proposal of a Novel Design Method for Inter-Channel Crosstalk in High-Density Optical Interconnects toward Massively Parallel Co-Packaged Optics	2038
<i>Ryosuke Matsumoto, Yuki Atsumi, Takayuki Kurosu, Fumi Nakamura, Siim Heinsalu, Akihiro Noriki Satoshi Suda, Takeru Amano</i>	
Bumpless Flip-Chip (BFC) as a Next-Generation Interconnect Technology for the AI Era	2042
<i>Rabindra N. Das, Dan Oates, Alex Wynn, David Kim, Ravi Rastogi, Neel Parmar, Lenny Johnson Steven Weber, Mollie Schwartz</i>	
Thermally Functional Self-Activated Bonding for EUV-Compatible Backside Integration	2048
<i>Hayato Kitagawa, Taisuke Yamamoto, Jenyu Lee, Shuntaro Machida, Kazuhiro Yuasa, Shunsuke Teranishi Joichi Nishimura, Fumihiro Inoue</i>	
Electrodeposition of Aluminum on Direct Bonded Copper Substrates for Power Module Packaging	2056
<i>Thi Minh Anh Dao, Ming-Si Jian, Phuong Thao Hoang, Peng-Wei Chu, Chun-Hao Chen</i>	
Direct Transfer Bonding of Ultra-thin Warped Chips for Advanced Heterogeneous 3DIC Integration with Fine-pitch Direct/Hybrid Bonding	2060
<i>Ichiro Sano, Jun Kaneyasu, Shinya Takyu, Tomoka Kirihata, Takafumi Fukushima, Yoichiro Kurita</i>	
Through-Glass Via and Substrate Recess Technologies: Enabling Embedded Devices and Co Packaged Optics in Advanced Glass Packaging	2067
<i>Nils Anspach, Jannis Heinz, Daniel Dunker, Norbert Ambrosius, Simon Hirt, Roman Ostholt</i>	
Void-Free, Low-Resistance Through-Glass Vias Formed Using a Reduction-Gas-Generating Sinterable Cu Paste	2073
<i>Murugesan Mariappan, Kiyoharu Mori, Hiroyuki Hashimoto, Harumi Hosogoe, Hirokatsu Sakamoto Akiko Happoya, Takafumi Fukushima</i>	
Time and Environment Characterization of Biodegradable Materials for Transient RF Systems	2080
<i>Denitsa G. Dimitrova, Pagnaa Attah Nantogmah, J. Carson Meredith, Manos M. Tentzeris</i>	
Impact of Cu density on via-to-via hybrid bonding: morphological and electrical characterizations	2086
<i>Agathe Lerat, Pablo Renaud, Christophe Dubarry, Margot Faure, Floriane Baudin, Sebastien Dominguez Hadi Hijazi, Yorrick Exbrayat, Frank Fournel</i>	
A Low-Cost 2.5D Photonic Silicon Interposer Assembly Process for HPC Applications	2093
<i>Digvijay Raorane, Suresh Pothukuchi, Ankur Aggarwal, Saket Chadda, Sagar Dubey, Dan Oh, Joy Zhan</i>	

Exploring Cu-Cu Hybrid Bonding Failure Mechanisms under Current Stress via 3D Focused Ion Beam Tomography	2100
<i>Sari Al Zerey, Junghyun Cho, Nicholas Polomoff, Roy Yu, Katsuyuki Sakuma</i>	
An Evaluation of Hybrid Bonding of Cu/SiO ₂ using Vacuum Ultraviolet Light under Redox Gases	2105
<i>Shinichi Endo, Wu Kejun, Kengo Nishio, Akihiro Shimamoto, Akihiro Shimizu</i>	
Novel O ₂ /H ₂ Plasma Treatment for Cu Oxide Removal and Dielectric Activation in Hybrid Bonding	2110
<i>Kazutaka Noda, Atsushi Nagata, Christopher Netzbant, Andrew Tuchman, Ilseok Son, Norifumi Kohama Yoshihiro Kondo</i>	
Fine pitch thermally resistive superconducting 3D interconnects for quantum systems	2117
<i>Pablo Renaud, Candice Thomas, Meriem Guergour, Nathan Portatiu Cambusset, Charles Bon-Mardion Edouard Deschaseaux, Hadi Hijazi, Laurent Truong, Richard Souil, François Aussenac, Jean Charbonnier</i>	
Comprehensive Characterization of Surface Activation for Chip-to-Wafer Hybrid Bonding in 3D Flash Memory	2124
<i>Jingqi Zhang, Bungo Tanaka, Murugesan Mariappan, Chang Liu, Tetsu Tanaka, Takafumi Fukushima</i>	
High-Throughput Metrology of CMP-treated Surface Topography using Fizeau Interferometry for Hybrid Bonding	2131
<i>Ryoichi Sato, Hashimoto Hiroyuki, Bungo Tanaka, Kota Sasaki, Murugesan Mariappan, Nishiyama Kohei Yuki Fujii, Tetsu Tanaka, Takafumi Fukushima</i>	
Interfacial Analysis of Hybrid Bonding Using Water Surface Tension-Driven Self-Assembly for HBM	2137
<i>Kota Sasaki, Bungo Tanaka, Ryoichi Sato, Hayato Hishinuma, Tetsu Tanaka, Takafumi Fukushima</i>	
Advanced Metrology for Heterogeneous Chiplet Integration with High-Speed 100% Bond Overlay Measurement	2143
<i>Tan Pham-Duy Nguyen, Bhaskar Jyoti Krishnatreya, Frank Bögelsack, Thomas Uhrmann, Siyan Dong Madhav Gautam, Elisabeth Brandl</i>	
Understanding Scaling and Temperature Limits in Cu Bulge-Out Mechanism for Hybrid Wafer-to-Wafer Bonding	2148
<i>Joke De Messemaeker, Boyao Zhang, Aleksandar Radisic, Zaid El-Mekki, Sven Dewilde Stefaan Van Huylenbroeck, Koen Van Sever, Herbert Struyf, Joeri De Vos, Gerald Beyer, Eric Beyne Zsolt Tókei</i>	
Die-Shift of Sub-20 μm Thickness Embedded Chiplet in Glass-Core Package Redistribution Layers	2153
<i>Hyunggyu Park, Jaewon Lee, Muhannad S. Bakir</i>	
Implanted Nanotwin Boundaries Enable Stable Hybrid-Bondable Copper Metallization	2160
<i>Abdelhamid El-Sawy, Pingping Ye, Jianwen Han, Stephan Braye, Harshul Khanna, David Doughty Veronica Lambert, Adam Letize, Adam Letize, Kyle Whitten, Thomas Richardson, Elie Najjar</i>	
A Compact Optical Engine With Novel 2D Thin Film Micro-VCSEL Array Architecture for CPO and LPO Application at 3.2 Tbps	2164
<i>Cheng-Kang Lee, Yuk-Tong Cheng, Tzu-Hung Lin, Wang-Shi Yu, Chi-Hsiang Ho, Jr-Hau He</i>	
Introduction to High-Speed LVDS Twisted Pair Transmission Across PCB and Chiplet RDL Interfaces	2168
<i>Mayukh Nandy, James Doyle, Simon Mayberry, Siyang Liu, Anuj Sarode, Hongbin Yu</i>	
Direct Chip Bonding on Thin Glass Substrates for W-Band Applications Using Aerosol Jet Printing	2173
<i>Ethan Kepros, Bhargav Avireni, Premjeet Chahal</i>	

Low-Temperature Sintering and Bonding Performance of Gradient Oxidized Copper Nanoparticles	2178
<i>Tetsu Yonezawa</i>	
Reliability Assessment of Liquid Metal Alloy Thermal Interface Materials in Fan-Out Embedded Bridge (FO-EB) Packages	2182
<i>Wen-Yu Teng, Jyun-De Jhan, Dai-Fei Li, Shane Lin, Yung-Ta Li, Andrew Kang, Don-Son Jiang</i>	
Electroless Noble Metal Passivation Enabling Oxidation-Free Cu Bonding through a Comparative Study of Au, Pd and Ru for Low-Temperature Hybrid Bonding Applications	2188
<i>Byeongchan Go, Hoogwan Lee, Keiyu Komamura, Takanori Kishida, Sarah Eunkyung Kim</i>	
Metal–Polymer Hybrid Bonding for Contamination Mitigation in Polymer-Based Semiconductor Packaging	2192
<i>Dong Yun Sung, Jiyun Lee, Seoyeon Choi, Seul Ki Hong</i>	
Challenges and Solutions for Package-level Encapsulation of Ultra-large Die Complexes	2196
<i>Yang Guo, Ziyin Lin, John C. Decker, James Breyfogle, Eylul Simsek, Hsin-Yu Li, Yiqun Bai, Chengzi Huang, Wen Yang</i>	
Evaluating Large Body Packaging Performance of Glass Core Substrates for AI and HPC Applications	2202
<i>JongMin Park, DongSu Ryu, GookJin Jung, JaeMin Bae, YoungSeob Shin, YoungHo Oh, YeonKi Jeong</i>	
Current-Assisted Cu–Cu Bonding at Low Temperature: Process Window and Mechanism	2209
<i>Byungkwan Kwak, Jinmyeong Seo, Haneul Han, Sanghwa Yoon, Bongyoung Yoo</i>	
Correlation of Copper Pattern Surface Morphology and Insertion Loss for High-Speed Communication	2214
<i>Yasutaka Amitani, Shunsuke Arima, Keisuke Joko</i>	
Microstructure for Zero Void by Control of Cu ²⁺ in Metallization for TGV of Glass Core Substrate	2221
<i>Sung-Bin Kim, Jae-Hyung Kim, Myung-Jun Kim, Kyeong-Seop Park, So-Yeon Lee</i>	
Robust LCP Bonding for Medical Implants: Impact of Surface Roughness and Reactive Accelerated Aging	2228
<i>Ladan Gocman Jiracek-Sapieha, Ryan Scott Wilkerson, Jack William Judy</i>	
A study of lithography process comparison for Co-Package Optics	2235
<i>Hironobu Fujishima, Koya Mita, Makoto Ogosu, Hiromi Suda, Ken-Ichiro Mori</i>	
Collective Die-to-Wafer Bonding of Si Dies and 4-Inch Polycrystalline Diamond Wafer with Ultralow Thermal Boundary Resistance and High Bonding Quality	2240
<i>Shuchao Bao, Ningning Xu, Ran He, Yi Zhong, Daquan Yu</i>	
Overcoming BEOL Thermal Constraints Via Low-Temperature Cu–Cu and Cu–Oxide Bonding of α -Ga ₂ O ₃ UV-C Photodetectors	2246
<i>Ji Yun Lee, Dong Yun Sung, Seoyeon Choi, Seoul Ki Hong</i>	
Scalable Construction of 3D Graphene Frameworks via Combined Foaming and Freeze-Drying in High-Performance Epoxy Nanocomposites for Advanced Packaging	2251
<i>Zihao Lin, Sung-Ting Chen, Jung Yi Chen, Kyoung-Sik Moon, C. P. Wong</i>	
A Low Profile DC-DC Converter on the Inductor-Embedded-Substrate as an integrated Package Solution (L-type-iPaS) Substrate for Next Vertical Power Delivery	2256
<i>Nobuyoshi Adachi, Yoshimitsu Ushimi, Kenji Nishiyama, Manabu Yano, Koshi Himeda, Atsushi Yamamoto</i>	

A Novel Capacitor Embedded Substrate Based on Capacitor-Type integrated Package Solution (iPaS) for Vertical Power Delivery in Advanced Semiconductor Packaging	2261
<i>Akitomo Takahashi, Shuhei Yamada, Yuuki Yabuhara, Manabu Yano, Kazuki Itoyama, Koshi Himeda Atsushi Yamamoto</i>	
Technology for Sequential Integration of HPA and LNA on Stacked GaN Layers for 3D Packaging of Next Gen Miniaturized Power RF Transceiver Front Ends	2268
<i>Kai Zoschke, Hermann Oppermann, Antonios Stavrinidis, Nikolaos Makris, Philomela Komninou Nikoletta Florini, Paolo Fioravanti, Errikos Lourandakis, Bruno Heusdens, Adrien Hertay Mohamad Abo Ras, Afshin Ziaei</i>	
Radar System-in-Package with Integrated Antennas based on Fan-Out Wafer-Level Packaging RDL-First Integration	2276
<i>Arnaud Garnier, Laetitia Castagné, Jean-Charles Souriau, Rémi Franiatte, Daniel Mermin Alexandre Siligaris, Mykhailo Zarudniev, Maciej Smierzchalski, Francesco Foglia Manzillo Perceval Coudrain</i>	
Sub-Millimeter GaN-on-Si Dielet Fabrication in Advanced Packaging Substrates Using Femtosecond Laser for 3D Heterogeneous Integration Applications	2283
<i>Pradyot Yadav, Xingchen Li, Danish Baig, Wanshu Zeng, Juan Pastrana-Gonzalez, Ahmad Islam Ulrich L. Rohde, Ruonan Han, Madhavan Swaminathan, Muhannad Bakir, Tomás Palacios</i>	
Room-temperature Reduction of Molybdenum Oxide via 172-nm Vacuum Ultraviolet Irradiation in an H ₂ /N ₂ Atmosphere with H ₂ O Vapor	2288
<i>Akihiro Shimizu, Shinichi Endo</i>	
High-Performance Low-Temperature SiCN for Hybrid Bonding in Advanced 3D Integration	2293
<i>Guanyu Song, Ming Li, Yuchen Hou, Hu Kang, Chunhai Ji</i>	
Silicon Bridges for Chiplets Heterogeneous Integration with Microbumps	2298
<i>John H Lau, Ning Liu, Tzyy-Jang Tseng</i>	
Enhanced Bonding Strength via Single-Wafer Annealing with Reduced Thermal Budget	2306
<i>Yoocharn Jeon, Mariia Gorchichko, Shashank Sharma, Jacob Yagura, Vijay Sukumaran, Juniper Iler Raghav Sreenivasan, Siddarth Krishnan, Michael Chudzik</i>	
Assembly Process Development for Ultra-large 88x52mm size Fan-Out Interposer with Bridge Chips to integrate Multi-HPC, HBM, and Photonic Optical Engine Chiplets	2310
<i>Sharon Pei Siang Lim, Lai Yee Chia, Manyi Pan, Hipona Randy Tupaen, Ignatius Lim Mohamed Zakir Hussain Mohamed Ishak, Jerald Soh, Sandra San, YongLiang Ye, Tai Chong Chai</i>	
Fine Pitch and Ultra Low Profile Double-side Molded LGA Solution	2316
<i>Ming-Hung Chen, Yu-Chang Chen, Ren-Jieh Kao, Yun-I Yeh</i>	
Thermo-Pressing Treatment to Enhance Conductivity of Printed Carbon on Flexible Substrates	2320
<i>Babatunde Falola, Riadh Al-Haidari, Olya Noruz Shamsian, Shiwantha Gunathilake, Mark D. Poliks</i>	
Integration of Novel PECVD Film as Inter-Die-Gap-Fill (IDGF) and Advanced Thermal Interface Materials (TIM) for Next Generation 3DICs	2328
<i>Vijay Sukumaran, Sean M Seutter, Karthik Guda Vishnu, Yoocharn Jeon, Michel Khoury, Grayson Langham Liu Jiang, Man-Ping Cai, Ying Trickett, El Mehdi Bazizi, Jinho An, Chris H Lee, Tom Osterheld Raghav Sreenivasan, Siddarth Krishnan, Michael Chudzik</i>	

Evaluation of Electroless-Plated Copper Circuits on Polyethylene Terephthalate (PET) for Roll-to-Roll Manufacturing of Flexible Hybrid Electronics	2334
<i>Zhi Dou, Riadh Al-Haidari, Mousa Al-Zanina, Mark J. Schadt, James Honan, Thomas LeBlanc, Emily Rej Carolyn Ellinger, Fabian Schnegg, Mark D. Poliks</i>	
Temperature-Dependent Electrical Characterization of New ABF-Type A Material Up to 220 GHz	2342
<i>Mahin Ahamed, Lakshmi Narasimha Vijay Kumar, Madhavan Swaminathan, Habib Hichri Yoshio Nishimura, Takashi Yamanaka, Yuko Shibata</i>	
Modular 3D Heterogeneous Integration with Stacked-Via 3D Stitch-Chips (SV-3DSC)	2349
<i>Shane Oh, Zhonghao Zhang, Paul K. Jo, Muhannad S. Bakir</i>	
60GHz mmWave Radar in Fan-In Wafer-Level Chip Scale Package (FI-WCSP) Technology	2354
<i>Aditya Jogalekar, Mohammad Vatankeh Varnosfaderani, Marc Dewilde, Karan Bhatia, Tim Davis Sangamesh Anandwade, Sunhwan Jang, Arnab Das, Vivek Sridharan, Krishnanshu Dandu Venkatesh Srinivasan</i>	
Organics-free Porous Nano-dendritic Cu Films for High-Power Packaging Interconnects	2359
<i>Fatin Battal, Nikhil Gupta, Ruben Pranger, Jeroen Maasen, Peter Mulder, René Poelma, Elias Vlieg John Schermer</i>	
Ground Resonance Suppression on 212.5-Gbps OSFP with FEM and Mixed-Mode dPBTL Circuit	2366
<i>Kewei Song, Shixuan Yuan, Yulin He, Xiangyi Kong, Joseph Wang, Milton Feng</i>	
Location-Dependent Microstructure and Mechanical Properties Evolution of TGV-Cu via an EBSD–Nanoindentation Co-Localization Characterization	2374
<i>Junwei Chen, Xiao Hu, Bin Yang, Chao Gu, Xuyang Yan, Chengqiang Cui, Guoqi Zhang, Jiajie Fan</i>	
Robust Design of Hybrid Bonding Considering Cu Pad Inelastic Deformation for Reliability	2382
<i>Sang-Hoon Kim, Yeoun-Soo Kim, Haeri Kim, Jong Han Shin, Jiho Kang, Eun-Ho Lee</i>	
Thermal Distribution Analysis of a 2.5D CPO Structure Integrated with a DFB Laser	2388
<i>Thu Huong Bui, Lucas Yang, Kung-An Lin, Chao-Hsin Wu</i>	
Reliability Evaluation of Intense Pulsed Light Flip-Chip Bonding with Various Surface Finishes	2393
<i>Hyeong-Bin Park Hanyang, Young-Min Ju, Yun-Joong Kim, Hak-Sung Kim</i>	
Enhancing SiO ₂ Bonding strength with Minimized Cu Surface Oxidation via H ₂ O-assisted Plasma Treatment	2400
<i>Gyeongyeol Lee, Youngjoon Cha, An Nguyen, Rino Choi</i>	
Low Temperature and Low Pressure Fine-pitch Cu-Cu Bonding by Electroplated In-Sn-Passivation	2405
<i>Yu-Hsiang Lu, Po-Shao Shih, Wei Choong Lee, Cheng-Yan Yang, Yun-Ching Hung, Yung-Sheng Lin Chen-Chao Wang, Chih-Pin Hung, C. Robert Kao</i>	
Miniaturized 3D Marchand Balun on Glass for Wideband RF Integration	2411
<i>Seokyoung Hwang, Sojeong Kim, Yubin Kim, Jongmin Yook, Gangtae Jin, Jein Yu, Young-Joon Kim</i>	
Next-Generation Scanning Electron Microscope for Advanced Packaging: Coating-Free, Ambient, and Ready-to-Use	2416
<i>Weichen Zhao, Junbo Yang, Yuhan Gao, Dalei Yang, Kewei Shou, Yi Deng, Karthik Arun Deo, Stephen Cain Seungbae Park, Donghwa Kwak, Yong-Eun Kwon, Junhee Lee</i>	

High Fidelity Reliability Prediction of SAC Solder Under Drop Impact via High Strain Rate and Temperature Dependent Properties	2424
<i>Dong-Hoon Yoo, You-Gwon Kim, Jin-Young Bang, Jong-Bum Lee, Hak-Sung Kim</i>	
3D Interconnection Using TGVs on Glass Interposer for Vertical 32 Gbps High-Speed Transmission	2431
<i>Suin Chae, Seonwoo Kim, Yubin Kim, Jaemyung Lim, Jein Yu</i>	
Reliability Prediction of Automotive SiC MOSFET Packages Based on Degradation of EMC Viscoelasticity and Interfacial Strength	2436
<i>Se-Min Lee, Se-Jun Park, Hee-Ju Han, Hyun-Woo Jung, Kyung-Woo Lee, Dae-Un Sung, Hongyun So Hak-Sung Kim</i>	
Towards High-Conductivity Aerosol Jet Printed Copper with Amine Surfactant	2443
<i>Cheng Zheng, Alfred A. Zimm, Chee Lip Gan</i>	
Ultra-low Coefficient of Thermal Expansion Spin-on Polymer for Deep Trench Gap-Filling for 3D-IC Heterogeneous Integration	2448
<i>Pin-Lin Chen, Yachien Chuang, Hsiaowei Yeh, Satoshi Fujimura, Chih Chen</i>	
Design and Signal Integrity Analysis of PCIe 5.0 SFF-8639 (U.2) Connector for AI Data Servers	2454
<i>Byeongmok Kim, Eunji Seo, Jihun Kim, Junho Park, Jiwon Yoon, Jaegeun Bae, Youngsu Yoon Hyunseo Uhm, Youngje Cho, Hyanggon Kim, Sungmin Choi, Joungho Kim</i>	
Novel CMP-Free Cu/Polymer Low Temperature Hybrid Bonding with Wide Process Window for Advanced Packaging and 3D Integration	2458
<i>Kai-Yu Chao, Yen-An Chen, Mu-Ping Hsu, Yuan-Chiu Huang, Chee-Ping Lee, Audrey Charles Kuan-Neng Chen</i>	
Room-temperature Au-Au Bonding of Rough-surface Ceramics Smoothed by Au Thin Film Transfer and the Plastic Deformation of Intermediate Metal Layer	2463
<i>Shintaro Goto, Kai Takeuchi, Eiji Higurashi</i>	
Advanced Acoustic Emission (AE) Sensing and Analytics Scheme for In-situ Warpage Characterizations of Flip-Chip Packaging	2467
<i>Yigit Turan, Xinchun Wang, Sathya Raghavan, Zimo Wang</i>	
Board-Level Reliability of 100mm × 100mm Large Glass Packages: Die Placement Configuration Based Thermo-Mechanical Reliability for AI/HPC Applications	2475
<i>Kaushik U. Godbole, YongWon Lee, Muhannad S. Bakir, Suresh K. Sitaraman</i>	
Direct Glass-Copper Vias Integrated with Blind-Cavity Embedded Chips using Nanoscale Liner	2483
<i>Sai Saravanan Ambi Venkataramanan, Mohanalingam Kathaperumal, Hyunggyu Park, Mruga Panse Aparnaa Iyer, Zhaoxia Yang, Mark Broman, Ching-Ping Wong, Mark D Losego</i>	
Plasma-Free Wafer-Level Hybrid Bonding Using iCVD Polymer Thin Film for Feasible 3D Multi-Chip Integration	2491
<i>Hyungjun Kim, Taehun Jeon, Jongkyung Park, Minju Kim</i>	
Interfacial Engineering for Cost-Effective Cu-to-Cu Direct Bonding Using an Ultra-Thin Cu-Selective Passivation Coating	2495
<i>Kevin Antony Jesu Durai, Duwage Anushka Sandaruwan Perera, Khanh Tuyet Anh Tran Dinesh Kumar Kumaravel, Shinoj Sridharan Nair, Rachel Ko, Oliver M.R. Chyan</i>	
Photonic Dielet Integration into Electrically Active FlexTrate™ for High Bandwidth Connectors	2501
<i>Alexis Samoylov, Subramanian S. Iyer</i>	

Ultraprecise Additive Printing of Reliable Fine-Pitch Features	2506
<i>Olya Noruz Shamsian, Erik Busse, Abdullah S. Obeidat, Mark D. Poliks</i>	
Compact 6-GHz Microstrip Bandpass Filter with Folded-Arm Resonators and Dual Transmission Zeros: Design, Fabrication and Measurement	2513
<i>Jaehyuk Lee, Alexander Wilcher, Hanna Jang, Ariel David, Yong-Kyu Yoon</i>	
Strain Range Dependent Fatigue Behavior of High Temperature Solder Alloys	2518
<i>Sean Y. Lai, Chung-Shuo Lee, Lijia Xie, John E. Blendell, Carol A Handwerker, Ganesh Subbarayan</i>	
A Novel Hierarchical Global Multi-Scale Network for X-ray Image Enhancement in Packaging	2524
<i>Hanwen Li, Nagarajan Raghavan, Senthilnath Jayavelu</i>	
Die-level Via-last TSV formation and Heterogeneous 3D Integration with Multi-Project Wafers Using Photosensitive Temporary Adhesives for Agile Prototyping	2532
<i>Jiayi Shen, Akihiro Tominaga, Bungo Tanaka, Chang Liu, Tetsu Tanaka, Takafumi Fukushima</i>	
Additively-Deposited Fan-Out Interconnects for Power/RF Co-Packaging with Glass-Laminate Hybrid Panels	2538
<i>Sajith Rathnayaka, Gilbert Rodriguez, Ronald van Olmen, Daniel Roque De Escobar, Arjuna Madanayake Markondeya Raj Pulugurtha</i>	
Novel Immersion-Sn Passivation Process to Address Nanoporous-Cu Seed Layer Etching Challenge for Scalable, Low-Temperature Panel-Level Cu-Cu Bonding	2543
<i>Ramón A. Sosa, Vanessa Smet, Antonia Antoniou, Jobert van Eijden, Kuldip Johal</i>	
Heterogeneous Integration of BEOL 22nm CMOS FDSOI Al to Cu Interposers by Direct Bonding	2548
<i>Kirthika Nahalingam, Mohammad Rezaeifer, Kamran Entesari, Linda Katehi</i>	
Link Quality Aware Pathfinding for Chiplet Interconnects	2555
<i>Aaron Yen, Jooyeon Jeong, Puneet Gupta</i>	
Thermally-Aware System-Technology Co-Optimization for AI Systems	2563
<i>Dedeepyo Ray, George Karfakis, Alexander Graening, David Ratchkov, Puneet Gupta</i>	
High-Resolution Nanoscale X-ray Imaging for Non-Destructive Inspection of Copper Grains in Fine-Pitch Pads for Hybrid Bonding	2570
<i>Nimish Prashant Nazirkar, Nicholas Polomoff, Roy Yu, Katsuyuki Sakuma, James Lu, Dmitry Karpov Edwin Fohtung</i>	